



OPEN
Compute Project

OCP NIC 3.0 Design Specification

Version 0.01

Author: OCP Server Workgroup, OCP NIC subgroup



Table of Contents

1	Overview	7
1.1	License	7
1.2	Background	8
1.3	Acknowledgements	9
1.4	Overview	9
1.4.1	Mechanical Form factor overview	9
1.4.2	Electrical overview	12
1.5	References	12
2	Card Form Factor	14
2.1	Overview	14
2.2	Form Factor Options	14
2.3	I/O bracket	16
2.4	Line Side I/O Implementations	16 ¹⁶
2.5	LED Implementations	17
2.5.1	Baseboard LEDs Configuration Over the Scan Chain	17
2.5.2	Add-in Card LED Configuration	19 ¹⁹
2.5.3	LED Ordering	20 ²⁰
2.6	Mechanical Keepout Zones	21 ²¹
2.6.1	Baseboard Keep Out Zones	21 ²¹
2.6.2	Add-in Card Keep Out Zones	21 ²¹
2.7	Labeling Requirements	21 ²¹
2.8	Insulation Requirements	21 ²¹
2.9	NIC Implementation Examples	21 ²¹
2.10	Non-NIC Use Cases	21 ²¹
2.10.1	PCIe Retimer card	21 ²¹
2.10.2	Accelerator card	21 ²¹
2.10.3	Storage HBA / RAID card	21 ²¹
3	Card Edge and Baseboard Connector Interface	22²²
3.1	Gold Finger Requirement	22 ²²

3.1.1	Gold Finger Mating Sequence.....	232
3.2	Baseboard Connector Requirement.....	262
3.3	Pin definition.....	272
3.4	Signal Descriptions – Common.....	333
3.4.1	PCIe Interface Pins.....	333
3.4.2	PCIe Present and Bifurcation Control Pins.....	373
3.4.3	SMBus Interface Pins.....	393
3.4.4	Power Supply Pins.....	404
3.4.5	Miscellaneous Pins.....	424
3.5	Signal Descriptions – OCP Bay (Primary Connector).....	424
3.5.1	PCIe Interface Pins – OCP Bay (Primary Connector).....	434
3.5.2	NC-SI Over RBT Interface Pins – OCP Bay (Primary Connector).....	454
3.5.3	Scan Chain Pins – OCP Bay (Primary Connector).....	515
3.5.4	Primary Connector Miscellaneous Pins – OCP Bay (Primary Connector).....	615
3.6	PCIe Bifurcation Mechanism.....	626
3.6.1	PCIe Add-in Card to Baseboard Bifurcation Configuration (PRSNTA#, PRSNTB[3:0]#).....	636
3.6.2	PCIe Baseboard to Add-in Card Bifurcation Configuration (BIF[2:0]#).....	636
3.6.3	PCIe Bifurcation Decoder.....	646
3.6.4	Bifurcation Detection Flow.....	666
3.6.5	PCIe Bifurcation Examples.....	676
3.7	PCIe Clocking Topology.....	737
3.8	PCIe Bifurcation Results and REFCLK Mapping.....	757
3.9	Power Capacity and Power Delivery.....	848
3.9.1	AC Power Off.....	858
3.9.2	ID Mode.....	858
3.9.3	Aux Power Mode (S5).....	858
3.9.4	Main Power Mode (S0).....	858
3.10	Power Supply Rail Requirements.....	858
3.11	Hot Swap Considerations for 12V and 3.3V Rails.....	868
3.12	Power Sequence Timing Requirements.....	878
4	Management.....	898
4.1	SMBus Interface.....	898



4.2	NC-SI Sideband Interface.....	8986
4.2.1	NC-SI addressing and Arb#.....	8986
4.3	MAC Address Requirement.....	8986
4.4	FRU EEPROM.....	8986
4.4.1	Minimum EEPROM Size.....	8986
4.4.2	EEPROM Map Definition.....	8986
4.4.3	EEPROM Address.....	9086
4.5	FW Requirement (TBD).....	9086
4.6	Thermal Reporting Interface.....	9086
5	Data Network Requirement.....	9187
5.1	Network Booting (collect view from OEMs and hyperscale).....	9187
6	Routing Guidelines and Signal Integrity Considerations.....	9288
6.1	NC-SI Over RBT.....	9288
7	Thermal and Environmental.....	9288
7.1	Environmental Requirements.....	9288
7.1.1	Thermal Simulation Boundary Example.....	9288
7.2	Shock & Vibration.....	9288
7.3	Regulation.....	9288
8	Revision History.....	9389

List of Figures

Figure 1: Representative Small OCP NIC 3.0 Card with Quad SFP Ports	8
Figure 2: Representative Large OCP NIC 3.0 Card with Dual QSFP Ports and on-board DRAM.....	9
Figure 3: Small and Large Card Form-Factors (not to scale).....	10
Figure 4: Example Small Card Form Factor	14
Figure 5: Example Large Card Form Factor.....	15
Figure 6: Primary Connector (4C + OCP Bay) with 4C and 2C Add-in Cards.....	16
Figure 7: LED Ordering – Example Small Card Link/Activity and Speed LED Placement.....	202
Figure 8: Small Size Primary Connector Gold Finger Mating Card Dimensions – x16 – Top Side.....	222
Figure 9: Small Size Primary Connector Gold Finger Mating Card Dimensions – x16 – Bottom Side.....	232
Figure 10: Large Size Card Gold Finger Mating Card Dimensions – x32 – Top Side	232
Figure 11: Large Size Card Gold Finger Mating Card Dimensions – x32 – Bottom Side.....	232
Figure 12: 168-pin Base Board Primary Connector – Right Angle	262
Figure 13: 140-pin Base Board Secondary Connector – Right Angle	262
Figure 14: 168-pin Base Board Primary Connector – Straddle Mount.....	262
Figure 15: 140-pin Base Board Secondary Connector – Straddle Mount.....	262
Figure 16: Primary and Secondary Connector Locations for Large Card Support.....	262
Figure 17: PCIe Present and Bifurcation Control Pins	383
Figure 18: Example Power Supply Topology	414
Figure 19: NC-SI Over RBT Connection Example	505
Figure 20: Scan Bus Connection Example	585
Figure 21: PCIe Bifurcation Pin Connections Support.....	636
Figure 22: Single Host (1 x16) and 1 x16 Add-in Card (Single Controller).....	676
Figure 23: Single Host (2 x8) and 2 x8 Add-in Card (Dual Controllers).....	686
Figure 24: Four Hosts (4 x4) and 4 x4 Add-in Card (Single Controller).....	696
Figure 25: Four Hosts (4 x4) and 4 x4 Add-in Card (Four Controllers).....	706
Figure 26: Single Host with no Bifurcation (1 x16) and 2 x8 Add-in Card (Two Controllers).....	727
Figure 27: PCIe Interface Connections for 1 x16 and 2 x8 Add-in Cards.....	737
Figure 28: PCIe Interface Connections for a 4 x4 Add-in Card.....	747
Figure 29: Baseboard Power States.....	848
Figure 30: Power Sequencing.....	878



List of Tables

Table 1: OCP 3.0 Form Factor Dimensions.....	10
Table 2: Baseboard to OCP NIC Form factor Compatibility Chart.....	11
Table 3: OCP NIC 3.0 Card Definitions.....	16
Table 4: OCP 3.0 Line Side I/O Implementations.....	1716
Table 5: Baseboard LED Configurations with Two Physical LEDs per Port.....	1818
Table 6: Add-in Card LED Configuration with Two Physical LEDs per Port.....	1919
Table 7: Contact Mating Positions for the Primary and Secondary Connectors.....	2423
Table 8: Primary Connector Pin Definition (x16) (4C + OCP Bay).....	2726
Table 9: Secondary Connector Pin Definition (x16) (4C).....	3130
Table 10: Pin Descriptions – PCIe 1.....	3332
Table 11: Pin Descriptions – PCIe Present and Bifurcation Control Pins.....	3736
Table 12: Pin Descriptions – SMBus.....	3938
Table 13: Pin Descriptions – Power.....	4039
Table 14: Pin Descriptions – Miscellaneous 1.....	4241
Table 15: Pin Descriptions – PCIe 2.....	4342
Table 16: Pin Descriptions – NC-SI Over RBT.....	4544
Table 17: Pin Descriptions – Scan Chain.....	5150
Table 18: Pin Descriptions – Scan Chain DATA_OUT Bit Definition.....	5452
Table 19: Pin Descriptions – Scan Bus DATA_IN Bit Definition.....	5453
Table 20: Pin Descriptions – Miscellaneous 2.....	6157
Table 21: PCIe Bifurcation Decoder for x16 and x8 Card Widths.....	6561
Table 22: PCIe Clock Associations.....	7369
Table 23: Bifurcation for Single Host, Single Socket and Single Upstream Link (BIF[2:0]#=0b000).....	7672
Table 24: Bifurcation for Single Host, Single Socket and Single/Dual Upstream Links (BIF[2:0]#=0b000).....	7773
Table 25: Bifurcation for Single Host, Single Socket and Single/Dual/Quad Upstream Links (BIF[2:0]#=0b000).....	7874
Table 26: Bifurcation for Single Host, Dual Sockets and Dual Upstream Links (BIF[2:0]#=0b001).....	7975
Table 27: Bifurcation for Single Host, Four Sockets and Dual Upstream Links (BIF[2:0]#=0b010).....	8076
Table 28: Bifurcation for Dual Host, Dual Sockets and Dual Upstream Links (BIF[2:0]#=0b101).....	8177
Table 29: Bifurcation for Quad Host, Quad Sockets and Quad Upstream Links (BIF[2:0]#=0b110).....	8278
Table 30: Bifurcation for Quad Host, Quad Sockets and Quad Upstream Links (BIF[2:0]#=0b110).....	8379
Table 31: Power States.....	8480
Table 32: Baseboard Power Supply Rail Requirements.....	8581
Table 33: Power Sequencing Parameters.....	8883

1 Overview

1.1 License

As of **April 7, 2011**, the following persons or entities have made this Specification available under the Open Web Foundation Final Specification Agreement (OWFa 1.0), which is available at <http://www.openwebfoundation.org/legal/the-owf-1-0-agreements/owfa-1-0>: Facebook, Inc.

You can review the signed copies of the Open Web Foundation Agreement Version 1.0 for this Specification at <http://opencompute.org/licensing/>, which may also include additional parties to those listed above.

Your use of this Specification may be subject to other third party rights. THIS SPECIFICATION IS PROVIDED "AS IS." The contributors expressly disclaim any warranties (express, implied, or otherwise), including implied warranties of merchantability, non-infringement, fitness for a particular purpose, or title, related to the Specification. The entire risk as to implementing or otherwise using the Specification is assumed by the Specification implementer and user. IN NO EVENT WILL ANY PARTY BE LIABLE TO ANY OTHER PARTY FOR LOST PROFITS OR ANY FORM OF INDIRECT, SPECIAL, INCIDENTAL, OR CONSEQUENTIAL DAMAGES OF ANY CHARACTER FROM ANY CAUSES OF ACTION OF ANY KIND WITH RESPECT TO THIS SPECIFICATION OR ITS GOVERNING AGREEMENT, WHETHER BASED ON BREACH OF CONTRACT, TORT (INCLUDING NEGLIGENCE), OR OTHERWISE, AND WHETHER OR NOT THE OTHER PARTY HAS BEEN ADVISED OF THE POSSIBILITY OF SUCH DAMAGE.



1.2 Background

The OCP NIC 3.0 specification is a follow-on to the OCP 2.0 form-factor for PCIe add-in cards. The OCP NIC 3.0 specification supports two basic card sizes: Small Card, and Large Card. The Small Card allows for up to 16 PCIe lanes on the card edge while a Large Card supports up to 32 PCIe. Compared to the OCP NIC 2.0 release, the updated specification provides a broader solution space for NIC and system vendors to support the following use case scenarios:

- NICs with a higher TDP
- Support up to 79W of power delivery to a single connector (Small) card; and 158W to a dual connector (Large) card
- PCIe Gen4 and Gen5 on the system and add-in card
- Support for upto 32 lanes of PCIe per add-in card
- Support for single host and multi-host environments
- Support a greater board area for more complex add-in card designs
- Support for Smart NIC implementations with on-board DRAM
- Simplification of FRU installation and removal while reducing overall down time

A representative Small Card OCP 3.0 NIC mezzanine card is shown in Figure 1 and a representative Large Card is shown in Figure 2.

Figure 1: Representative Small OCP NIC 3.0 Card with Quad SFP Ports

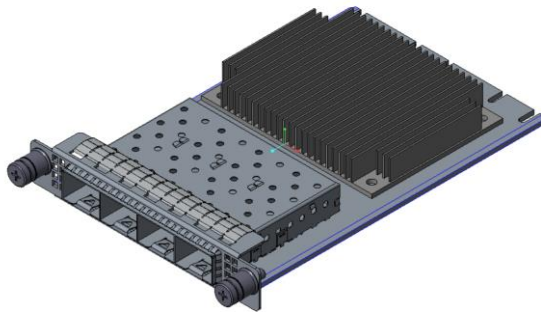
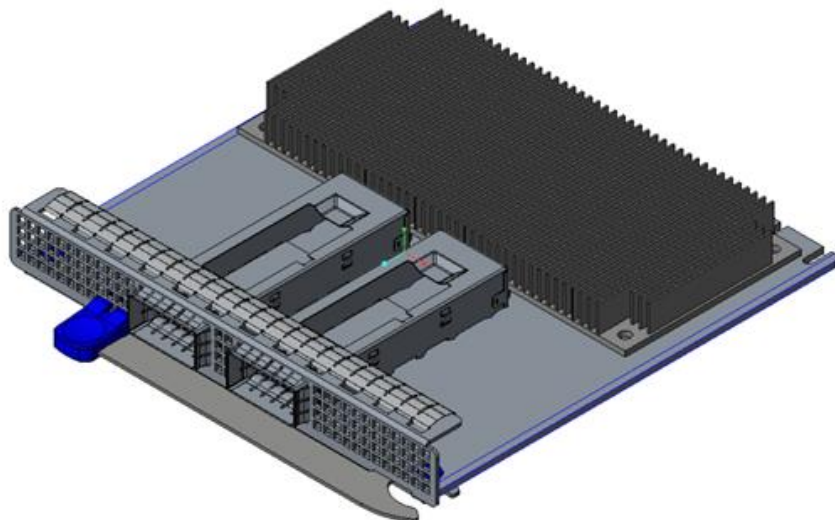


Figure 2: Representative Large OCP NIC 3.0 Card with Dual QSFP Ports and on-board DRAM



In order to achieve the features outlined in this specification, OCP 3.0 compliant cards are not backwards compatible to the 2.0 cards.

This specification is created under OCP Server workgroup – OCP NIC subgroup. An electronic copy of this specification can be found on the Open Compute Project website:

http://www.opencompute.org/wiki/Server/Mezz#Specifications_and_Designs

1.3 Acknowledgements

Placeholder

1.4 Overview

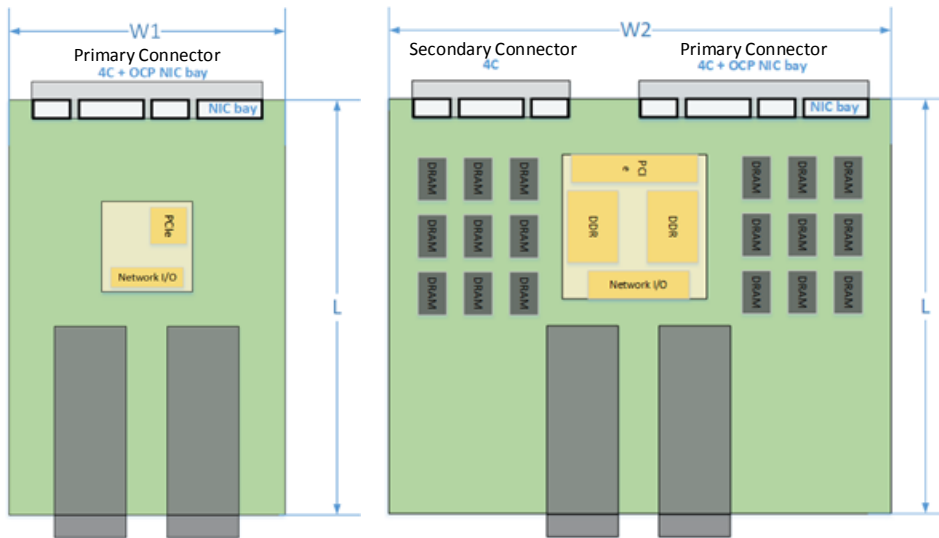
1.4.1 Mechanical Form factor overview

The OCP NIC 3.0 specification defines a third generation mechanical form factor that allows for interoperability between compliant baseboards and add-in cards.



OCP NIC 3.0 cards have two form factors – Small and Large. These cards are shown in Figure 3 below. The components shown in the figures are for illustrative purposes. The Small form factor card has one connector (Primary connector) on baseboard. The Large form factor card has two connectors (Primary Connector and Secondary Connector) on the baseboard. Both the Primary and Secondary connectors are defined in and compliant to SFF-TA-1002. [Editor's note: plan to submit change back to SFF-TA-1002]. On the NIC side, the card edge is implemented with gold fingers. The gold finger design follows SFF-TA-1002 as well.

Figure 3: Small and Large Card Form-Factors (not to scale)



The two form factor dimensions are shown in Table 1.

Table 1: OCP 3.0 Form Factor Dimensions

Form Factor	Width	Depth	Primary Connector	Secondary Connector	Typical Use Case

Small	W1 = 76 mm	L = 115 mm	4C + OCP sideband 168 pins	N/A	Low profile and general NIC with a similar profile as an OCP NIC 2.0 add-in card; up to x16 PCIe.
Large	W2 = 139 mm	L = 115 mm	4C + OCP sideband 168 pins	4C 140 pins	Larger PCB width to support feature rich NICs; up to x32 PCIe.

The OCP NIC 3.0 design allows downward compatibility between the two card sizes. Table 2 shows the compatibility between the baseboard and NIC combinations. A small size baseboard slot may only accept a small sized NIC. A Large size baseboard slot may accept a small or large sized NIC.

Table 2: Baseboard to OCP NIC Form factor Compatibility Chart

Baseboard Slot Size	NIC Size / Supported PCIe Width	
	Small	Large
Small	Up to x16	Not Supported
Large	Up to x16	Up to x32

There are two baseboard connector options available for system designers: straddle mount and right angle (RA). The straddle mount connector option allows the OCP NIC and baseboard to exist in a co-planer position. To achieve this, a cutout exists on the baseboard and is defined in this specification. Alternatively, the right angle option allows the OCP NIC to be installed on top of the baseboard. A baseboard cutout is not required for the right angle connector. The right angle option allows the baseboard to use this area for additional routing or backside component placement. The straddle mount and right angle connectors are shown in Section 3.2.

For both the baseboard and OCP card, this specification defines the component and routing keep out areas. Refer to Section 2.6 for details.

Both the straddle mount and right angle implementations shall accept the same OCP add-in card and shall be supported in the baseboard chassis regardless of the baseboard connector



selection (right angle or straddle mount) so long as the baseboard slot side and add-in card sizes are a supported combination as shown in Table 2.

This specification defines the form factor at the add-in card level, including the front panel, latching mechanism and card guide features [TBD; pending on the Mechanical work across stakeholders].

More details about the card form-factor is shown in Section 2.

1.4.2 Electrical overview

This specification defines the electrical interface between baseboard and the add-in card.

The electrical interface is implemented with a right angle or straddle mount connector on baseboard and gold finger on the add-in card. As previously noted in the mechanical overview, each card may implement a Primary Connector or Primary + Secondary Connector. Cards using only the Primary connector are suitable for both the Small and Large form-factors and may support up to x16 lanes of PCIe. The Secondary connector, when used in conjunction with the Primary connector, allows Large form-factor implementations and may support up to 32 lanes of PCIe.

1.4.2.1 Primary Connector

1.4.2.2 Secondary connector

1.5 References

- DMTF Standard. *DSP0222, Network Controller Sideband Interface (NC-SI) Specification*. Distributed Management Task Force, Inc, Rev 1.0.1, January 24th, 2013.
- EDSFF. *Enterprise and Datacenter SSD Form Factor Connector Specification*. Enterprise and Datacenter SSD Form Factor Working Group, Rev 0.9 (draft), August 2nd 2017.
- NXP Semiconductors. *PC-bus specification and user manual*. NXP Semiconductors, Rev 6, April 4th, 2014.

Commented [TN1]: References need to be correctly sited per MLA standards.

Q: How do we handle references to unpublished (draft) specifications?

- Open Compute Project. *OCP NIC Subgroup*. Online.
<http://www.opencompute.org/wiki/Server/Mezz>
- PCIe Base Specification. *PCI Express Base Specification, Revision 4.0 (draft)*.
- PCIe CEM Specification. *PCI Express Card Electromechanical Specification, Revision 4.0 (draft)*.
- SMBus Management Interface Forum. *System Management Bus (SMBus) Specification*. System Management Interface Forum, Inc, Version 3.0, December 20th, 2014.
- SNIA. *SFF-TA-1002, Specification for Protocol Agnostic Multi-Lane High Speed Connector*. SNIA SFF TWG Technology Affiliate, Rev 0.0.9.1, September 9th, 2017.



2 Card Form Factor

2.1 Overview

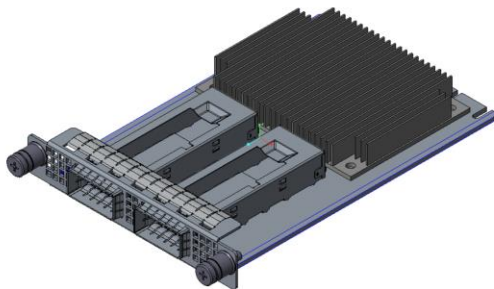
2.2 Form Factor Options

OCP3.0 provides two fundamental form factor options: a small card (76mm x 115mm) and a large card (139mm x 115mm).

These form factors support a Primary Connector and optionally, a Secondary Connector. The Primary Connector is defined to be a SFF-TA-1002 compliant 4C connector plus a 28-pin bay for OCP 3.0 specific pins. The Secondary Connector is the 4C connector as defined in SFF-TA-1002. The 4C specification supports up to 32 differential pairs for a x16 PCIe connection per connector. For host platforms, the 28-pin OCP bay is required for the Primary connector. This is also mandatory for add-in cards.

The small card uses the 4C connector for up to a x16 PCIe interface. The small cards implement an additional 28-pin OCP bay for management functions and support for up to a four PCIe hosts. The small size card provides sufficient faceplate area to accommodate up to 2x QSFP modules, 4x SFP modules, or 4x RJ-45 for BASE-T operation. The small card form factor supports up to 79W of delivered power to the card edge.

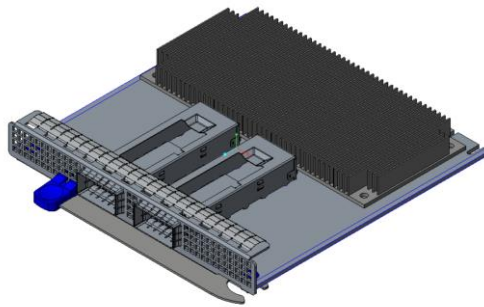
Figure 4: Example Small Card Form Factor



Commented [TN2]: Are we going to uprev the SFF-TA spec to include these 28 pins?

The large card uses provides the same functionality as the small card, but with support up to a x32 PCIe interface. The large card utilizes both the Primary and Secondary connectors. The large size card supports higher power envelopes and provides additional board area for more complex designs. The small card form factor supports up to 158W of delivered power to the card edge at 79W per connector.

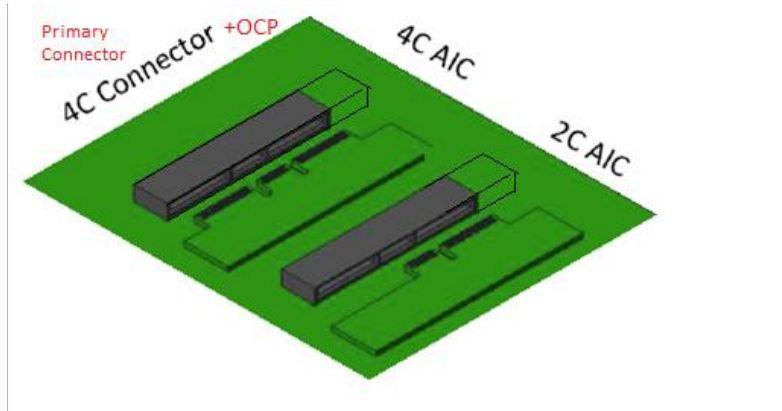
Figure 5: Example Large Card Form Factor



For both form-factors, an add-in card may optionally implement a subset of pins to support a x8 PCIe connection. This is implemented using a 2C card edge per SFF-TA-1002. The Primary Connector may support a 2C sized add-in card along with the 28 pin OCP bay. The following diagram from the SFF-TA-1002 specification illustrates the supported host Primary and Secondary Connectors and add-in card configurations.



Figure 6: Primary Connector (4C + OCP Bay) with 4C and 2C Add-in Cards



Commented [TN3]: This needs to be updated to show the OCP bay along with the secondary connector location..

Table 3

Primary Connector and up to 16 PCIe lanes. Large form factor cards support both the Primary and Secondary Connectors and up to 32 PCIe lanes.

Table 3 summarizes the supported card form factors. Small form factors cards support the Primary Connector and up to 16 PCIe lanes. Large form factor cards support both the Primary and Secondary Connectors and up to 32 PCIe lanes.

Table 3: OCP NIC 3.0 Card Definitions

Add in Card Size and max PCIe Lane Count	Secondary Connector		Primary Connector	
	4C Connector, x16 PCIe		4C Connector, x16 PCIe	OCP Bay
Small (x8)			2C	OCP Bay
Small (x16)			4C	OCP Bay
Large (x24)		2C	4C	OCP Bay
Large (x32)	4C		4C	OCP Bay

2.3 I/O bracket

TBD <need input from OCP mechanical groups>

2.4 Line Side I/O Implementations

At the time of this writing, the Small and Large form-factor cards may support the following standard line side I/O implementations:

Table 4: OCP 3.0 Line Side I/O Implementations

Form Factor	Max Topology Connector Count
Small	2x QSFP28
Small	4x SFP28
Small	4x RJ-45
Large	TBD
Large	TBD
Large	TBD

Additional combinations are permissible as I/O form-factor technologies and thermal capabilities evolve.

2.5 LED Implementations

LEDs must be implemented on the card Scan Chain (as defined in Section 3.5.3) for remote link/activity indication on the baseboard and may optionally be implemented on the OCP NIC 3.0 I/O bracket if there is sufficient space for local indication. These two cases are described below. In both cases, the actual link rate may be directly queried through the management interface.

2.5.1 Baseboard LEDs Configuration Over the Scan Chain

A small form-factor OCP NIC 3.0 with a fully populated I/O bracket (2x QSFP28, 4x SFP28, or 4x RJ-45) has insufficient space for discrete on-board (faceplate) LED indicators. In this case, the line side link and activity LED indicators are implemented on the baseboard system via the Scan Chain. The Scan Chain bit stream is defined in Section 3.5.3. This LED implementation is required for all add-in cards. The baseboard LED implementation uses two discrete LEDs (Link/Activity and Speed indication).

~~For small form-factor low I/O count cards (such as 1x QSFP28, 2x SFP28, or 2x RJ-45), or a large form factor OCP 3.0 NIC, where additional I/O bracket area is available, the card may optionally implement on-board link/activity indications in addition to the Scan Chain.~~



For both cases, the OCP NIC 3.0 specification recommends the following LED definitions:
[Table 5 describes the baseboard LED configuration for baseboard implementations.](#)

Table 5: ~~Default Baseboard LED Configuration-s~~ with Two Physical LEDs per Port

LED Pin	LED Color	Description
Link / Activity	Green	<p><u>Active low. Multifunction LED.</u></p> <p><u>When lit and solid, this LED is used to indicate the link is up at the MAC level. Local and Remote Faults are clear and the link is ready for data transmission.</u></p> <p><u>When the LED is off, the physical link is down or disabled.</u></p> <p><u>The LED should blink low for 50-500 ms during Packet Activity.</u></p> <p><u>The Link/Activity LED shall be located on the left hand side for each port.</u>Active low. Multifunction LED.</p> <p>When lit and solid, this LED is used to indicate the link is up at the MAC level. Local and Remote Faults are clear and the link is ready for data transmission. When the LED is off, the physical link is down or disabled.</p> <p>This LED indicator may also be used for port identification through vendor specific link diagnostic software.</p> <p>The link LED shall be located on the left hand side of each port.</p>
	Off	<p><u>Active low. Multifunction LED.</u></p> <p><u>The LED is Green when the port is linked at its maximum speed.</u></p> <p><u>The LED is off when the device is linked at a speed lower than the highest capable speed, or no link is present.</u></p>
Speed	Green	<p><u>Active low. Multifunction LED.</u></p> <p><u>The LED is Green when the port is linked at its maximum speed.</u></p> <p><u>The LED is off when the device is linked at a speed lower than the highest capable speed, or no link is present.</u></p>



		<u>The bicolor speed LED shall be located on the right hand side for each port.</u>
--	--	---

At the time of this writing, the Scan Chain definition allows for up to one link/activity and one activity-speed LED per port. A total of up to 8 ports are supported in the Scan Chain. The bit stream defines the LEDs to be active low (ON). The Scan Chain LED implementation allows the NIC LED indicators to be remotely located on the OCP 3.0 compliant chassis (e.g. front LED indicators with rear I/O cards).

2.5.2 Add-in Card LED Configuration

For low I/O count small form-factor low I/O count cards without built in light pipes (such as 1x QSFP28, 2x SFP28, or 2x RJ-45), or a large form-factor OCP 3.0 NIC, where additional I/O bracket area is available, the card may optionally implement on-board link/activity indications in addition to the Scan Chain LED stream. The recommended local (on-card) LED implementation uses two physical LEDs (a discrete Link/Activity LED and a bi-colored Speed A/Speed B LED). Table 6 describes the add-in card LED implementations.

Table 6: Add-in Card LED Configuration with Two Physical LEDs per Port

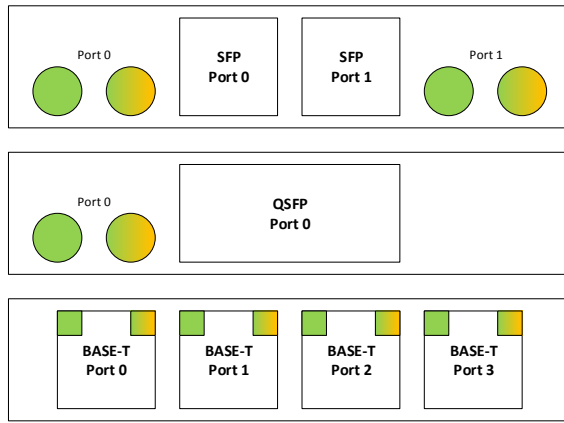
<u>LED Pin</u>	<u>LED Color</u>	<u>Description</u>
<u>Link / Activity</u>	<u>Green</u>	<u>Active low. Multifunction LED.</u> <u>When lit and solid, this LED is used to indicate the link is up at the MAC level. Local and Remote Faults are clear and the link is ready for data transmission.</u> <u>When the LED is off, the physical link is down or disabled.</u> <u>The LED should blink low for 50-500 ms during Packet Activity.</u>

		<u>The Link/Activity LED shall be located on the left hand side for each port.</u>
<u>Speed</u>	<u>Green</u>	<u>Active low. Bicolor multifunction LED.</u> <u>The LED is Green when the port is linked at its maximum speed.</u> <u>The LED is Amber when the port is linked at it second highest speed.</u> <u>The LED is off when the device is linked at a speed lower than the second highest capable speed, or no link is present.</u> <u>The Amber Speed LED indicator may be used for port identification through vendor specific link diagnostic software.</u> <u>The bicolor speed LED shall be located on the right hand side for each port.</u>
	<u>Amber</u>	
	<u>Off</u>	

2.5.3 LED Ordering

For all LED use cases, the green Link/Activity LED shall be located on the left side for each port. The bicolor green/amber speed A/B LED shall be located on the right side for each port. (Note Speed B is only available for local (on-card) LEDs. The placement of the LEDs may be to the side of the physical port for the case with add-in cards. The LED port association shall be clearly labeled on the add-in card and on the baseboard.

Figure 7: LED Ordering – Example Small Card Link/Activity and Speed LED Placement



2.6 Mechanical Keepout Zones

2.6.1 Baseboard Keep Out Zones

TBD – Need keepout drawings and envelopes for small / large size baseboard including primary/secondary/rail keepouts/cutout for straddle mount/keepout for right angle.

2.6.2 Add-in Card Keep Out Zones

TBD – need keepout drawings and envelopes for small / large size NIC including primary/secondary/rail keepouts.

2.7 Labeling Requirements

TBD

2.8 Insulation Requirements

All cards must implement a secondary side insulator to prevent the bottom side card components from shorting out to the chassis. The recommended insulator thickness is 0.25mm and must reside within the following mechanical envelope for the Small and Large size cards:

TBD <need 2D drawings>

2.9 NIC Implementation Examples

TBD

2.10 Non-NIC Use Cases

“PCIe interface with extra management sideband”

2.10.1 PCIe Retimer card

2.10.2 Accelerator card

2.10.3 Storage HBA / RAID card

3 Card Edge and Baseboard Connector Interface

3.1 Gold Finger Requirement

The OCP NIC 3.0 add-in cards are compliant to the SFF-TA-1002 specification with respect to the gold fingers and connectors.

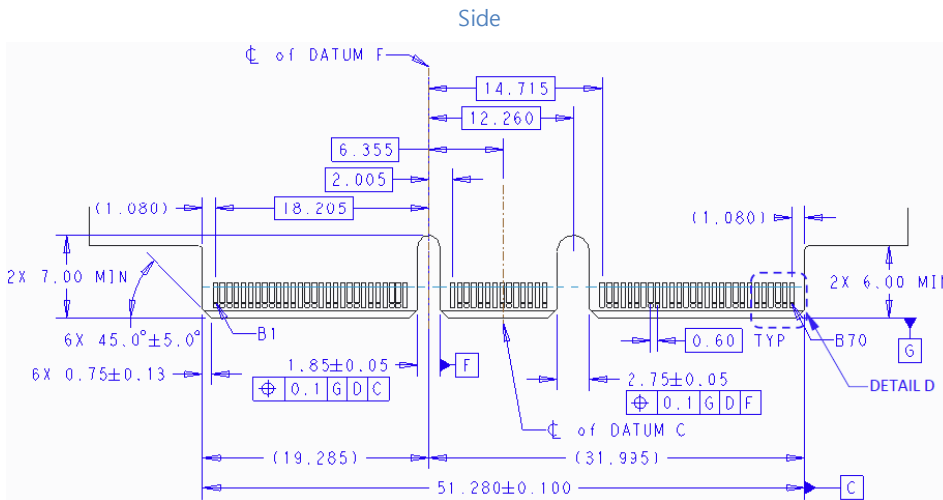
Small Size cards fit in the Primary Connector. Primary Connector compliant cards are 76mm x 115mm and may implement the full 168-pins. The Primary Connector cards may optionally implement a subset of gold finger pins if there is a reduced PCIe width requirement (such as 1 x8 and below). In this case, the card edge gold finger may implement a 2C design. The overall board thickness is 1.60mm. The gold finger dimensions for the Primary Connector compliant cards are shown below.

Large Size Cards support up to a x32 PCIe implementation and uses both the Primary and Secondary connectors.

For additional details, refer to the card and connector mechanical drawings located in XXX.

Note: The “B” pins on the connector are associated with the top side of the add-in card. The “A” pins on the connector are associated with the bottom side of the add-in card.

Figure 87: Small Size Primary Connector Gold Finger Mating Card Dimensions – x16 – Top



Commented [TN4]: Drawing was pulled from SFF-TA-1002 FIGURE 5-18.

Figure 98: Small Size Primary Connector Gold Finger Mating Card Dimensions – x16 –

Side
TBD

Commented [TN5]: Drawing was pulled from SFF-TA-1002 FIGURE 5-18.

Figure 109: Large Size Card Gold Finger Mating Card Dimensions – x32 – Top Side

TBD

Commented [TN6]: Drawing was pulled from SFF-TA-1002 FIGURE 5-18.

Figure 114: Large Size Card Gold Finger Mating Card Dimensions – x32 – Bottom Side

TBD

Commented [TN7]: Drawing was pulled from SFF-TA-1002 FIGURE 5-18.

3.1.1 Gold Finger Mating Sequence

Per the SFF-TA-1002 specification, the Primary and Secondary connectors are protocol agnostic and are optimized for high speed differential pairs. For use in the OCP NIC 3.0 application, some pin locations are used for single ended control nets or power and would benefit from a shorter pin length for staggering. As such, the recommended add-in card gold finger staging is shown in [Table 7](#) ~~Table 6~~ for a two stage, first-mate, last-break. The host connectors have a single stage mating and do not implement different pin lengths.

The AIC Plug (Free) side refers to the add-in card gold fingers; the receptacle (Fixed) side refers to the physical connector on the host platform. This table is based on the SFF-TA-1002 Table A-1 with modifications for OCP NIC 3.0. Refer to the mechanical drawings for pin the first-mate and second-mate lengths.

Table 76: Contact Mating Positions for the Primary and Secondary Connectors

Side B			Side A		
AIC Plug (Free)		Receptacle (Fixed)	AIC Plug (Free)		Receptacle (Fixed)
2 nd Mate	1 st Mate		2 nd Mate	1 st Mate	
OCP B1	Yellow	Blue	OCP A1	Yellow	Blue
OCP B2	Yellow	Blue	OCP A2	Yellow	Blue
OCP B3	Yellow	Blue	OCP A3	Yellow	Blue
OCP B4	Yellow	Blue	OCP A4	Yellow	Blue
OCP B5	Yellow	Blue	OCP A5	Yellow	Blue
OCP B6	Yellow	Blue	OCP A6	Green	Blue
OCP B7	Yellow	Blue	OCP A7	Yellow	Blue
OCP B8	Yellow	Blue	OCP A8	Yellow	Blue
OCP B9	Yellow	Blue	OCP A9	Yellow	Blue
OCP B10	Green	Blue	OCP A10	Green	Blue
OCP B11	Yellow	Blue	OCP A11	Yellow	Blue
OCP B12	Yellow	Blue	OCP A12	Yellow	Blue
OCP B13	Green	Blue	OCP A13	Green	Blue
OCP B14	Yellow	Blue	OCP A14	Yellow	Blue
Mechanical Key					
B1	Yellow	Blue	A1	Green	Blue
B2	Yellow	Blue	A2	Green	Blue
B3	Yellow	Blue	A3	Green	Blue
B4	Yellow	Blue	A4	Green	Blue
B5	Yellow	Blue	A5	Green	Blue
B6	Yellow	Blue	A6	Green	Blue
B7	Yellow	Blue	A7	Yellow	Blue
B8	Yellow	Blue	A8	Yellow	Blue
B9	Yellow	Blue	A9	Yellow	Blue
B10	Yellow	Blue	A10	Yellow	Blue
B11	Yellow	Blue	A11	Yellow	Blue
B12	Yellow	Blue	A12	Yellow	Blue
B13	Green	Blue	A13	Green	Blue
B14	Yellow	Blue	A14	Yellow	Blue
B15	Yellow	Blue	A15	Yellow	Blue
B16	Green	Blue	A16	Green	Blue
B17	Yellow	Blue	A17	Yellow	Blue
B18	Yellow	Blue	A18	Yellow	Blue
B19	Green	Blue	A19	Green	Blue
B20	Yellow	Blue	A20	Yellow	Blue
B21	Yellow	Blue	A21	Yellow	Blue
B22	Green	Blue	A22	Green	Blue



B23			A23		
B24			A24		
B25			A25		
B26			A26		
B27			A27		
B28			A28		
Mechanical Key					
B29			A29		
B30			A30		
B31			A31		
B32			A32		
B33			A33		
B34			A34		
B35			A35		
B36			A36		
B37			A37		
B38			A38		
B39			A39		
B40			A40		
B41			A41		
B42			A42		
Mechanical Key					
B43			A43		
B44			A44		
B45			A45		
B46			A46		
B47			A47		
B48			A48		
B49			A49		
B50			A50		
B51			A51		
B52			A52		
B53			A53		
B54			A54		
B55			A55		
B56			A56		
B57			A57		
B58			A58		
B59			A59		
B60			A60		
B61			A61		
B62			A62		
B63			A63		
B64			A64		
B65			A65		
B66			A66		
B67			A67		
B68			A68		
B69			A69		
B70			A70		

3.2 Baseboard Connector Requirement

The OCP NIC 3.0 connectors are compliant to the “4C connector” as defined in the SFF-TA-1002 specification for a right angle or straddle mount form-factor. The 4C connector is 140-pins in width and includes support for up to 32 differential pairs to support a x16 PCIe connection. The connector also provides 6 pins of 12V for payload power. This implementation is common between both the Primary and Secondary Connectors. In addition, the Primary Connector has a 28-pin OCP Bay to the right of pin 1. These pins are used for management and support for up to a 4 x4 multi-host configuration on the Primary Connector. The Primary and Secondary Connector drawings are shown in [Figure 12](#)[Figure 13](#)[Figure 12](#), [Figure 14](#)[Figure 13](#) and [Figure 15](#)[Figure 14](#) below.

Figure 12: 168-pin Base Board Primary Connector – Right Angle

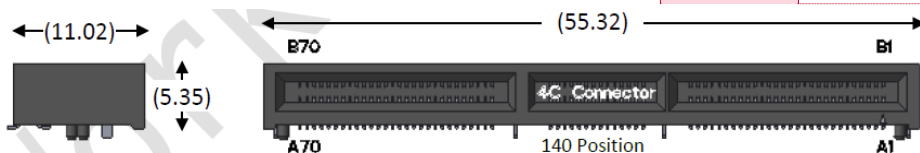


Figure 13: 140-pin Base Board Secondary Connector – Right Angle

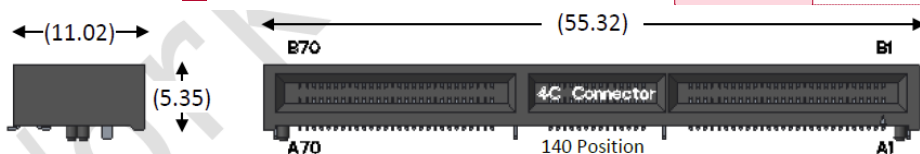


Figure 14: 168-pin Base Board Primary Connector – Straddle Mount

TBD

Figure 15: 140-pin Base Board Secondary Connector – Straddle Mount

TBD

In order to support the large form factor, systems must locate the Primary and Secondary Connectors per the mechanical drawing shown in [Figure 16](#)[Figure 15](#).

Figure 16: Primary and Secondary Connector Locations for Large Card Support

TBD

Commented [TN8]: Note: Perhaps the SFF-TA-1002 spec needs to be updated with the 168 pin and straddle-mount definitions.

Commented [TN9]: Get updated drawing from TE with the straddle mount option.

Commented [TN10]: Get updated drawing from TE with the straddle mount option.

Commented [TN11]: Get updated drawing from TE with the straddle mount option.

Commented [TN12]: Get updated drawing from TE with the straddle mount option.



3.3 Pin definition

The pin definitions of an OCP NIC 3.0 card with up to a x32 PCIe interface are shown in [Table 8](#)~~Table 7~~ and [Table 9](#)~~Table 8~~. All signal directions are shown from the perspective of

A baseboard system may provide a combination of Primary Connectors only, or Primary and Secondary Connectors to support multiple sizes of add-in cards. Both connectors share common functionality with power, SMBus, x16 PCIe Gen4 and bifurcation control. The Primary Connector has an additional OCP Bay (pins OCP_A[1:14], OCP_B[1:14]) with additional REFCLKs for supporting up to four PCIe hosts, NC-SI connectivity and a Scan Chain for information exchange between the host and card. The NIC is required to implement the Scan Chain, while the baseboard may choose to optionally implement it. Depending on the baseboard form-factor, multiple OCP NIC 3.0 compliant cards may be designed into the system.

The pins common to the Primary and Secondary Connectors are shown in Section 3.4. The OCP Bay pins on the Primary Connector only are shown in Section 3.5.

Cards or systems that do not require the use of a PCIe x16 connection may optionally implement a subset electrical connections as applicable to the design. For example, a x8 (or smaller) card using the first 8 PCIe lanes that is compliant with the Primary Connector pinout. Refer to Sections 3.1 and 3.2 for mechanical details. For these cases, the Primary Connector matches the 2C dimensions as defined in SFF-TA-1002.

In all cases, the physical baseboard connectors shall support x16 PCIe widths and must be implemented with the Primary (4C + OCP Bay) and Secondary (4C) connectors.

[Table 8](#)~~7~~: Primary Connector Pin Definition (x16) (4C + OCP Bay)

Side B		Side A		Primary Connector (x16, 168-pin add-in)	Primary Connector (x8, 112-pin add-in)
OCP_B1	NIC_PWR_GOOD	WAKE_N	OCP_A1		
OCP_B2	PWRBRK#	PERST2#	OCP_A2		
OCP_B3	LD#	PERST3#	OCP_A3		
OCP_B4	DATA_IN	RBT_ARB_IN	OCP_A4		
OCP_B5	DATA_OUT	RBT_ARB_OUT	OCP_A5		
OCP_B6	CLK	GND	OCP_A6		

OCP_B7	SLOT_ID0	RBT_TX_EN	OCP_A7
OCP_B8	RBT_RXD1	RBT_TXD1	OCP_A8
OCP_B9	RBT_RXD0	RBT_TXD0	OCP_A9
OCP_B10	GND	GND	OCP_A10
OCP_B11	REFCLKn2	REFCLKn3	OCP_A11
OCP_B12	REFCLKp2	REFCLKp3	OCP_A12
OCP_B13	GND	GND	OCP_A13
OCP_B14	RBT_CRS_DV	RBT_CLK_IN	OCP_A14
Mechanical Key			
B1	+12V/+12V_AUX	GND	A1
B2	+12V/+12V_AUX	GND	A2
B3	+12V/+12V_AUX	GND	A3
B4	+12V/+12V_AUX	GND	A4
B5	+12V/+12V_AUX	GND	A5
B6	+12V/+12V_AUX	GND	A6
B7	BIF0#	SMCLK	A7
B8	BIF1#	SMDAT	A8
B9	BIF2#	SMRST#	A9
B10	PERST0#	PRSNTA#	A10
B11	+3.3V/+3.3V_AUX	PERST1#	A11
B12	PWRDIS	PRSNB2#	A12
B13	GND	GND	A13
B14	REFCLKn0	REFCLKn1	A14
B15	REFCLKp0	REFCLKp1	A15
B16	GND	GND	A16
B17	PETn0	PERn0	A17
B18	PETp0	PERp0	A18
B19	GND	GND	A19
B20	PETn1	PERn1	A20
B21	PETp1	PERp1	A21
B22	GND	GND	A22
B23	PETn2	PERn2	A23
B24	PETp2	PERp2	A24
B25	GND	GND	A25
B26	PETn3	PERn3	A26
B27	PETp3	PERp3	A27
B28	GND	GND	A28
Mechanical Key			
B29	GND	GND	A29

Commented [TN13]: Jia brought up a good point about PRSNTA#

Unlike PCIe, the PRSNTA / PRSNB indication doesn't necessarily help us with an x-axis alignment. The Present signals may still connect.

Perhaps we could connect PRSNB pins to GND instead of PRSNTA? This would free up a pin for use. (As a bonus, pin A10 is a bidirectional pin (based on function) per EDSFF).



B30	PETn4	PERn4	A30
B31	PETp4	PERp4	A31
B32	GND	GND	A32
B33	PETn5	PERn5	A33
B34	PETp5	PERp5	A34
B35	GND	GND	A35
B36	PETn6	PERn6	A36
B37	PETp6	PERp6	A37
B38	GND	GND	A38
B39	PETn7	PERn7	A39
B40	PETp7	PERp7	A40
B41	GND	GND	A41
B42	PRSNB0#	PRSNB1#	A42
Mechanical Key			
B43	GND	GND	A43
B44	PETn8	PERn8	A44
B45	PETp8	PERp8	A45
B46	GND	GND	A46
B47	PETn9	PERn9	A47
B48	PETp9	PERp9	A48
B49	GND	GND	A49
B50	PETn10	PERn10	A50
B51	PETp10	PERp10	A51
B52	GND	GND	A52
B53	PETn11	PERn11	A53
B54	PETp11	PERp11	A54
B55	GND	GND	A55
B56	PETn12	PERn12	A56
B57	PETp12	PERp12	A57
B58	GND	GND	A58
B59	PETn13	PERn13	A59
B60	PETp13	PERp13	A60
B61	GND	GND	A61
B62	PETn14	PERn14	A62
B63	PETp14	PERp14	A63
B64	GND	GND	A64
B65	PETn15	PERn15	A65
B66	PETp15	PERp15	A66
B67	GND	GND	A67

B68	RFU, N/C	RFU, N/C	A68	
B69	RFU, N/C	RFU, N/C	A69	
B70	PRSNTB3#	RFU, N/C	A70	



Table 98: Secondary Connector Pin Definition (x16) (4C)

Side B		Side A	
B1	+12V/+12V_AUX	GND	A1
B2	+12V/+12V_AUX	GND	A2
B3	+12V/+12V_AUX	GND	A3
B4	+12V/+12V_AUX	GND	A4
B5	+12V/+12V_AUX	GND	A5
B6	+12V/+12V_AUX	GND	A6
B7	BIF0#	SMCLK	A7
B8	BIF1#	SMDAT	A8
B9	BIF2#	SMRST#	A9
B10	PERST0#	PRSNTA#	A10
B11	+3.3V/+3.3V_AUX	PERST1#	A11
B12	PWRDIS	PRSNTB2#	A12
B13	GND	GND	A13
B14	REFCLKn0	REFCLKn1	A14
B15	REFCLKp0	REFCLKp1	A15
B16	GND	GND	A16
B17	PETn0	PERn0	A17
B18	PETp0	PERp0	A18
B19	GND	GND	A19
B20	PETn1	PERn1	A20
B21	PETp1	PERp1	A21
B22	GND	GND	A22
B23	PETn2	PERn2	A23
B24	PETp2	PERp2	A24
B25	GND	GND	A25
B26	PETn3	PERn3	A26
B27	PETp3	PERp3	A27
B28	GND	GND	A28
Mechanical Key			
B29	GND	GND	A29
B30	PETn4	PERn4	A30
B31	PETp4	PERp4	A31
B32	GND	GND	A32
B33	PETn5	PERn5	A33
B34	PETp5	PERp5	A34
B35	GND	GND	A35
B36	PETn6	PERn6	A36

Secondary Connector (x16, 140-pin add-in card)

Secondary Connector (x8, 84-pin add-in card)

B37	PETp6	PERp6	A37
B38	GND	GND	A38
B39	PETn7	PERn7	A39
B40	PETp7	PERp7	A40
B41	GND	GND	A41
B42	PRSNB0#	PRSNB1#	A42
Mechanical Key			
B43	GND	GND	A43
B44	PETn8	PERn8	A44
B45	PETp8	PERp8	A45
B46	GND	GND	A46
B47	PETn9	PERn9	A47
B48	PETp9	PERp9	A48
B49	GND	GND	A49
B50	PETn10	PERn10	A50
B51	PETp10	PERp10	A51
B52	GND	GND	A52
B53	PETn11	PERn11	A53
B54	PETp11	PERp11	A54
B55	GND	GND	A55
B56	PETn12	PERn12	A56
B57	PETp12	PERp12	A57
B58	GND	GND	A58
B59	PETn13	PERn13	A59
B60	PETp13	PERp13	A60
B61	GND	GND	A61
B62	PETn14	PERn14	A62
B63	PETp14	PERp14	A63
B64	GND	GND	A64
B65	PETn15	PERn15	A65
B66	PETp15	PERp15	A66
B67	GND	GND	A67
B68	RFU, N/C	RFU, N/C	A68
B69	RFU, N/C	RFU, N/C	A69
B70	PRSNB3#	RFU, N/C	A70



3.4 Signal Descriptions – Common

The pins shown in this section are common to both the Primary and Secondary Connectors. All pin directions are from the perspective of the baseboard.

The add-in card shall implement protection methods to prevent leakage paths between the Vaux and Vmain power domains in the event that a NIC is powered down in a powered up baseboard.

Note: Pins that are only used on Primary Connector 28-pin OCP bay are defined in Section 3.5.

3.4.1 PCIe Interface Pins

This section provides the pin assignments for the PCIe interface signals. The AC/DC specifications are defined in the PCIe CEM Specification, Rev 4.0. Example connection diagrams for are shown in [Figure 28](#)~~Figure-26~~.

Table 109: Pin Descriptions – PCIe 1

Signal Name	Pin #	Baseboard Direction	Signal Description
REFCLKn0 REFCLKp0	B14 B15	Output	PCIe compliant differential reference clock #0, and #1. 100MHz reference clocks are used for the add-in card PCIe core logic. For baseboards, the REFCLK0 and REFCLK1 signals are required at the connector. For add-in cards, the required REFCLKs shall be connected per the endpoint datasheet. Note: For cards that only support 1 x16, REFCLK0 is used. For cards that support 2 x8, REFCLK0 is used for the first eight PCIe lanes,
REFCLKn1 REFCLKp1	A14 A15	Output	

			and REFCLK1 is used for the second eight PCIe lanes. Refer to Section 2.1 in the PCIe CEM Specification, Rev 4.0 for electrical details.
PETn0 PETp0	B17 B18	Output	<p>Transmitter differential pairs [0:15]. These pins are connected from the baseboard transmitter differential pairs to the receiver differential pairs on the add-in card.</p> <p>The PCIe transmit pins are AC coupled on the baseboard with capacitors and are placed next to the baseboard transmitters. The AC coupling capacitor must be between 176nF (min) and 265nF (max).</p> <p>For baseboards, the PET[0:15] signals are required at the connector.</p> <p>For add-in cards, the required PET[0:15] signals shall be connected to the endpoint silicon. For silicon that uses less than a x16 connection, the appropriate PET[0:15] signals shall be connected per the endpoint datasheet.</p> <p>Refer to Section 6.1 in the PCIe CEM Specification, Rev 4.0 for details.</p>
PETn1 PETp1	B20 B21	Output	
PETn2 PETp2	B23 B24	Output	
PETn3 PETp3	B26 B27	Output	
PETn4 PETp4	B30 B31	Output	
PETn5 PETp5	B33 B34	Output	
PETn6 PETp6	B36 B37	Output	
PETn7 PETp7	B39 B40	Output	
PETn8 PETp8	B44 B45	Output	
PETn9 PETp9	B47 B48	Output	
PETn10 PETp10	B50 B51	Output	
PETn11 PETp11	B53 B54	Output	
PETn12 PETp12	B56 B57	Output	
PETn13 PETp13	B59 B60	Output	



PETn14	B62	Output	
PETp14	B63		
PETn15	B65	Output	
PETp15	B66		
PERn0	A17	Input	Receiver differential pairs [0:15]. These pins are connected from the add-in card transmitter differential pairs to the receiver differential pairs on the baseboard.
PERp0	A18		
PERn1	A20	Input	The PCIe receive pins are AC coupled on the add-in card with capacitors and are placed next to the add-in card transmitters. The AC coupling capacitor must be between 176nF (min) and 265nF (max).
PERp1	A21		
PERn2	A23	Input	For baseboards, the PER[0:15] signals are required at the connector.
PERp2	A24		
PERn3	A26	Input	For add-in cards, the required PER[0:15] signals shall be connected to the endpoint silicon. For silicon that uses less than a x16 connection, the appropriate PER[0:15] signals shall be connected per the endpoint datasheet.
PERp3	A27		
PERn4	A30	Input	Refer to Section 6.1 in the PCIe CEM Specification, Rev 4.0 for details.
PERp4	A31		
PERn5	A33	Input	
PERp5	A34		
PERn6	A36	Input	
PERp6	A37		
PERn7	A39	Input	
PERp7	A40		
PERn8	A44	Input	
PERp8	A45		
PERn9	A47	Input	
PERp9	A48		
PERn10	A50	Input	
PERp10	A51		
PERn11	A53	Input	
PERp11	A54		
PERn12	A56	Input	
PERp12	A57		
PERn13	A59	Input	
PERp13	A60		

PERn14 PERp14	A62 A63	Input	
PERn15 PERp15	A65 A66	Input	
PERST0# PERST1#	B10 A11	Output	<p>PCIe Reset #0, #1. Active low.</p> <p>Indicates when the applied power is within tolerance and stable for the add-in card. PERST# goes high at least 100ms after the power rails are within operating limits per the PCIe CEM Specification. The PCIe REFCLKs also become stable within this period of time. PERST is pulled high on the baseboard.</p> <p>For OCP NIC 3.0, PERST deassertion also indicates the full card power envelope is available to the add-in card.</p> <p>For baseboards, the PERST[0:1]# signals are required at the connector.</p> <p>For add-in cards, the required PERST[0:1]# signals shall be connected to the endpoint silicon.</p> <p>Note: For cards that only support 1 x16, PERST0# is used. For cards that support 2 x8, PERST0# is used for the first eight PCIe lanes, and PERST1# is used for the second eight PCIe lanes.</p> <p>Refer to Section 2.2 in the PCIe CEM Specification, Rev 4.0 for details.</p>



3.4.2 PCIe Present and Bifurcation Control Pins

This section provides the pin assignments for the PCIe present and bifurcation control signals. The AC/DC specifications are defined in Section XXX. An example connection diagram is shown in [Figure 17](#)~~Figure 16~~.

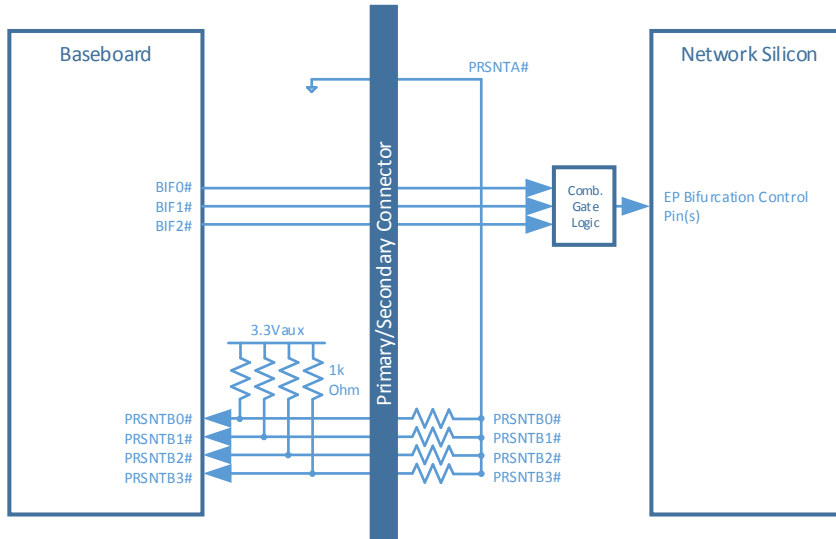
The PRSNTA#/PRSNTB[0:3]# state may be used to determine if a card has been physically plugged in. The PRSNTA#/PRSNTB[0:3]#/BIF[0:2]# pins must be latched at least 1 ms before PWRDIS deassertion of the system AC power on to ensure the correct values are detected by the system. Changing the pin states after this timing window is not allowed. Refer to the AC timing diagram in Section XXX for details.

Table ~~1140~~ 1140: Pin Descriptions – PCIe Present and Bifurcation Control Pins

Signal Name	Pin #	Baseboard Direction	Signal Description
PRSNTA#	A12	Output	Present A is used for add-in card presence and PCIe capabilities detection. For baseboards, this pin is directly connected to GND. For add-in cards, this pin is connected to the PRSNTB[3:0]# pins.
PRSNTB0# PRSNTB1# PRSNTB2# PRSNTB3#	B42 A42 A10 B70	Input	Present B [0:3]# are used for add-in card presence and PCIe capabilities detection. For baseboards, these pins are connected to the I/O hub and are pulled up to +3.3Vaux using 1kOhm resistors.

			<p>For add-in cards, these pins are strapped to PRSNTA#. The encoding definitions are described in Section 3.6.</p> <p>PRSNTB3# is located at the bottom of the 4C connector and is only applicable for add-in cards with a PCIe width of x16 (or greater). Add-in cards that implement a 2C card edge do not use the PRSNTB3# pin for capabilities or present detection.</p>
<p>BIF0# BIF1# BIF2#</p>	<p>A7 A8 A9</p>	<p>Output</p>	<p>Bifurcation [0:2]# pins allow the baseboard to force configure the add-in card bifurcation.</p> <p>For baseboards, these pins are outputs driven from the baseboard I/O hub and allows the system to force configure the add-in card bifurcation. The baseboard may optionally tie the BIF[0:2]# signals to 3.3Vaux or to ground if no dynamic bifurcation configuration is required.</p> <p>For add-in cards, these signals connect to the endpoint bifurcation pins if it is supported.</p> <p>The BIF[0:2]# encoding definitions are described in Section 3.6.</p> <p>Note: the required combinatorial logic output for endpoint bifurcation is dependent on the specific silicon and is not defined in this specification.</p>

Figure 1716: PCIe Present and Bifurcation Control Pins



3.4.3 SMBus Interface Pins

This section provides the pin assignments for the SMBus interface signals. The AC/DC specifications are defined in the SMBus and I²C bus specifications. An example connection diagram is shown in Figure XXX.

Table 1211: Pin Descriptions – SMBus

Signal Name	Pin #	Baseboard Direction	Signal Description
SMCLK	A7	Output, OD	<p>SMBus clock. Open drain, pulled up to 3.3Vaux on the baseboard.</p> <p>For baseboards, connect the SMCLK from the platform SMBus master to the connector.</p> <p>For add-in cards, connect the SMCLK from the endpoint silicon to the card edge gold fingers.</p>

SMDAT	A8	Input / Output, OD	SMBus Data. Open drain, pulled up to 3.3Vaux on the baseboard. For baseboards, connect the SMDAT from the platform SMBus master to the connector. For add-in cards, connect the SMDAT from the endpoint silicon to the card edge gold fingers.
SMRST#	A9	Output, OD	SMBus reset. Open drain. For baseboards, this pin is pulled up to 3.3Vaux and is used to reset optional downstream SMBus devices (such as temperature sensors). SMRST# is a mandatory signal for baseboard implementations. For add-in cards, SMRST# is optional.

3.4.4 Power Supply Pins

This section provides the pin assignments for the power supply interface signals. The AC/DC specifications are defined in the PCIe CEM Specification, Rev 4.0 and amended in Section 3.10. An example connection diagram is shown in [_Figure 18](#)~~Figure XXX~~.

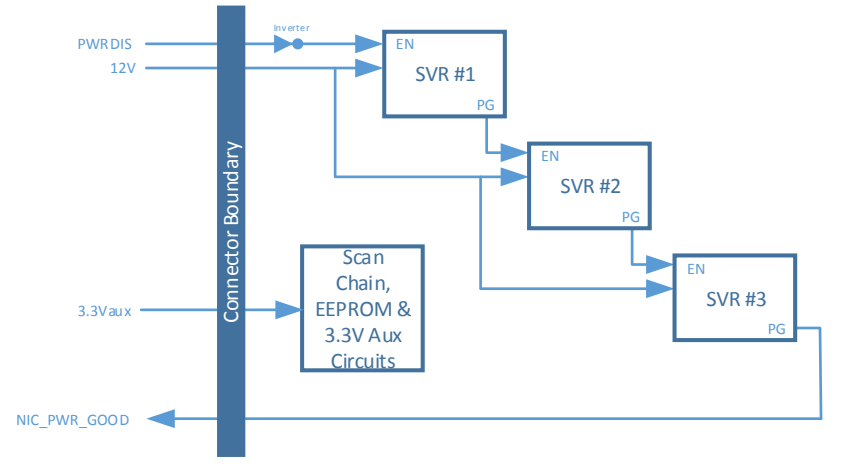
Table ~~1312~~: Pin Descriptions – Power

Signal Name	Pin #	Baseboard Direction	Signal Description
GND	Various	GND	Ground return; a total of 46 ground pins are on the main 140-pin connector area.
+12V/+12V_AUX	B1, B2, B3, B4, B5, B6	Power	12V main or 12V Aux power; total of 6 pins per connector. The 12V pins are rated to 1.1A per pin with a maximum derated power delivery of 79.2W.



			<p>The +12V power pins must be within the rail tolerances (TBD tolerance for Aux) when the PWRDIS pin is driven low by the baseboard.</p>
+3.3V/3.3V_AUX	B11	Power	<p>3.3V main or 3.3V Aux power; total of 1 pin per connector. The 3.3V pin is rated to 1.1A for a maximum derated power delivery of 3.63W.</p> <p>The 3.3Vaux/main power pin must be within the rail tolerances when the PWRDIS pin is driven low by the baseboard.</p>
PWRDIS	B12	Output, <u>O/D</u>	<p>Power disable. Active high. <u>Open-drain</u></p> <p>This signal is driven <u>pulled up to 3.3V through a 10kOhm resistor by-on</u> the baseboard.</p> <p>When high, all this signal notifies the <u>add-in card to turn off all supplies connected to +12V are disabled power.</u></p> <p>When low, this signal notifies the add-in card to enable the on-card power supplies <u>add-in card supplies are enabled.</u></p>

Figure 18: Example Power Supply Topology



3.4.5 Miscellaneous Pins

This section provides the pin assignments for the miscellaneous interface signals.

Table 1413: Pin Descriptions – Miscellaneous 1

Signal Name	Pin #	Baseboard Direction	Signal Description
RFU, N/C	B68, B69, A68, A69, A70	Input / Output	Reserved future use pins. Leave these pins as no connect.

3.5 Signal Descriptions – OCP Bay (Primary Connector)

The following section describes the functions in the Primary Connector 28-pin OCP bay. This 28-pin bay is shown in Section 3.3 and have pin numbers designated as OCP_B[1:14], and OCP_A[1:14]. All pin directions on this OCP bay are from the perspective of the baseboard.

The add-in card shall implement protection methods to prevent leakage paths between the Vaux and Vmain power domains in the event that a NIC is powered down in a powered up baseboard.



Note: The pins that are common to both the Primary and Secondary Connectors are defined in Section 3.4.

3.5.1 PCIe Interface Pins – OCP Bay (Primary Connector)

This section provides the pin assignments for the PCIe interface signals on the Primary Connector OCP bay. The AC/DC specifications are defined in Section XXX. An example connection diagram that shows REFCLK2, REFCLK3, PERST2# and PERST3# is shown in Section 3.7.

Table 1514: Pin Descriptions – PCIe 2

Signal Name	Pin #	Baseboard Direction	Signal Description
REFCLKn2 REFCLKp2	OCP_B11 OCP_B12	Output	PCIe compliant differential reference clock #2, and #3. 100MHz reference clocks are used for the add-in card PCIe core logic. For baseboards, the REFCLK2 and REFCLK3 signals are required at the Primary connector. For add-in cards, the required REFCLKs shall be connected per the endpoint datasheet. Note: REFCLK2 and REFCLK3 are not used for cards that only support a 1 x16 or 2 x8 connection. Refer to Section 2.1 in the PCIe CEM Specification, Rev 4.0 for details.
REFCLKn3 REFCLKp3	OCP_A11 OCP_A12	Output	
PERST2# PERST3#	OCP_A2 OCP_A3	Output	PCIe Reset #2, #3. Active low. Indicates when the applied power is within tolerance and stable for the add-in card.

			<p>PERST# goes high at least 100ms after the power rails are within operating limits per the PCIe CEM Specification. The PCIe REFCLKs also become stable within this period of time. PERST is pulled high on the baseboard.</p> <p>For OCP NIC 3.0, PERST deassertion also indicates the full card power envelope is available to the add-in card.</p> <p>For baseboards, the PERST[0:1]# signals are required at the connector.</p> <p>For add-in cards, the required PERST[0:1]# signals shall be connected to the endpoint silicon.</p> <p>Note: PERST2# and PERST3# are not used for cards that only support a 1 x16 or 2 x8 connection.</p> <p>Refer to Section 2.2 in the PCIe CEM Specification, Rev 4.0 for details.</p>
WAKE#	OCP_A1	Input, OD	<p>WAKE#. Open drain. Active low.</p> <p>This signal is driven by the add-in card to notify the baseboard restore the PCIe link. For add-in cards that support multiple WAKE# signals, their respective WAKE# pins may be tied together as the signal is open-drain to form a wired-OR.</p>



			<p>For baseboards, this signal is pulled up to +3.3V on the baseboard with a 10kOhm resistor and is connected to the system WAKE# signal.</p> <p>For add-in cards, this signal is connected directly to the endpoint silicon WAKE# pin(s).</p> <p>Refer to Section 2.3 in the PCIe CEM Specification, Rev 4.0 for details.</p>
--	--	--	--

3.5.2 NC-SI Over RBT Interface Pins – OCP Bay (Primary Connector)

This section provides the pin assignments for the NC-SI over RBT interface signals on the Primary Connector OCP bay. The AC/DC specifications are defined in the NC-SI specification. An example connection diagram is shown in [Figure 19](#)~~Figure 17~~.

For the purposes of this specification, the min and max electrical trace length of the NC-SI signals shall be between 2 inches and 4 inches. The traces shall be implemented as 50 Ohm impedance controlled nets.

Table ~~1615~~ Pin Descriptions – NC-SI Over RBT

Signal Name	Pin #	Baseboard Direction	Signal Description
RBT_CLK_IN	OCP_A14	Output	<p>Reference clock input. Synchronous clock reference for receive, transmit and control interface. The clock has a nominal frequency of 50MHz \pm100ppm.</p> <p>For baseboards, connect this pin between the baseboard NC-SI over RBT PHY and the connector. This signal requires a 100kOhm pull down resistor on the baseboard. If the</p>

			<p>baseboard does not support NC-SI over RBT, then terminate this signal to ground through a 100kOhm pull down resistor.</p> <p>For add-in cards, connect this pin from the gold finger to the endpoint silicon. Leave this pin as a no connect if NC-SI is not supported.</p>
RBT_CRSDV	OCP_B14	Input	<p>Carrier sense/receive data valid. This signal is used to indicate to the baseboard that the carrier sense/receive data is valid.</p> <p>For baseboards, connect this pin between the baseboard NC-SI over RBT PHY and the connector. This signal requires a 100kOhm pull down resistor on the baseboard. If the baseboard does not support NC-SI over RBT, then terminate this signal to ground through a 100kOhm pull down resistor.</p> <p>For add-in cards, connect this pin from the gold finger to the endpoint silicon. Leave this pin as a no connect if NC-SI is not supported.</p>
RBT_RXD0 RBT_RXD1	OCP_B9 OCP_B8	Input	<p>Receive data. Data signals from the network controller to the BMC.</p> <p>For baseboards, connect this pin between the baseboard NC-SI over RBT PHY and the connector. This signal requires a 100kOhm pull-up resistor to 3.3Vaux on the baseboard. If the baseboard does not support NC-SI over RBT, then terminate this signal to 3.3Vaux through a 100kOhm pull-up.</p>



			For add-in cards, connect this pin from the gold finger to the endpoint silicon. Leave this pin as a no connect if NC-SI is not supported.
RBT_TX_EN	OCP_A7	Output	<p>Transmit enable.</p> <p>For baseboards, connect this pin between the baseboard NC-SI over RBT PHY and the connector. This signal requires a 100kOhm pull down resistor to ground on the baseboard. If the baseboard does not support NC-SI over RBT, then terminate this signal to ground through a 100kOhm pull down.</p> <p>For add-in cards, connect this pin from the gold finger to the endpoint silicon. Leave this pin as a no connect if NC-SI is not supported.</p>
RBT_TXD0 RBT_TXD1	OCP_A9 OCP_A8	Output	<p>Transmit data. Data signals from the BMC to the network controller.</p> <p>For baseboards, connect this pin between the baseboard NC-SI over RBT PHY and the connector. This signal requires a 100kOhm pull-up resistor to 3.3Vaux on the baseboard. If the baseboard does not support NC-SI over RBT, then terminate this signal to 3.3Vaux through a 100kOhm pull-up.</p> <p>For add-in cards, connect this pin from the gold finger to the endpoint silicon. Leave this pin as a no connect if NC-SI is not supported.</p>
RBT_ARB_OUT	OCP_A5	Output	NC-SI hardware arbitration output. Used only if the end point silicon supports hardware

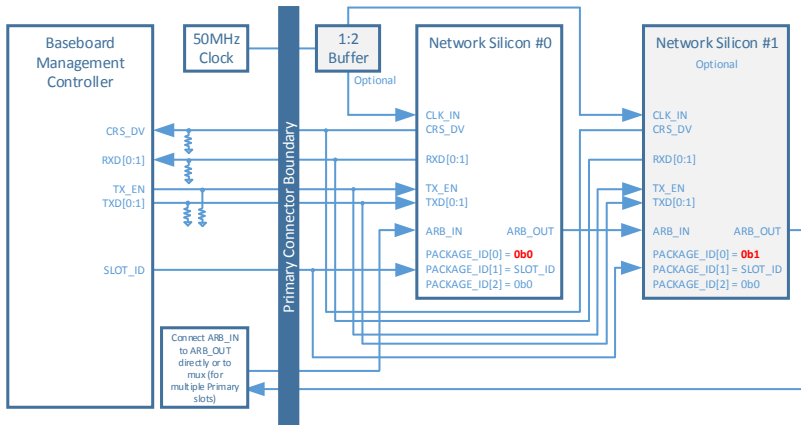
			<p>arbitration. Connects to the ARB_IN signal of an adjacent device.</p> <p>The ARB_IN pin is also routed to the card edge to allow multiple devices and OCP slots on the baseboard to share the NC-SI ring. The baseboard shall implement a multiplexing implementation that directs the RBT_ARB_OUT to the RBT_ARB_IN pin of the next NC-SI capable device in the ring, or back to the RBT_ARB_IN pin of the source device if there is a single device on the ring.</p> <p>For baseboards, connect this pin between the baseboard OCP connector(s) to complete the hardware arbitration ring. If the baseboard does not support NC-SI over RBT, connect this signal directly to the RBT_ARB_IN pin.</p> <p>For add-in cards, connect this pin from the gold finger to the endpoint silicon. Leave this pin as a no connect if NC-SI is not supported.</p>
RBT_ARB_IN	OCP_A4	Input	<p>NC-SI hardware arbitration input. Used only if the end point silicon supports hardware arbitration. Connects to the ARB_OUT signal of an adjacent device.</p> <p>The ARB_OUT pin is also routed to the card edge to allow multiple devices and OCP slots on the baseboard to share the NC-SI ring. The baseboard shall implement a multiplexing implementation that directs the RBT_ARB_IN to the RBT_ARB_OUT pin of the next NC-SI</p>



			<p>capable device in the ring, or back to the RBT_ARB_OUT pin of the source device if there is a single device on the ring.</p> <p>For baseboards, connect this pin between the baseboard OCP connector(s) to complete the hardware arbitration ring. If the baseboard does not support NC-SI over RBT, connect this signal directly to the RBT_ARB_OUT pin.</p> <p>For add-in cards, connect this pin from the gold finger to the endpoint silicon. Leave this pin as a no connect if NC-SI is not supported.</p>
SLOT_ID	OCP_B7	Output	<p>NC-SI Address pin. Used only if the end point silicon supports package identification.</p> <p>For baseboards, this pin is used to identify the slot ID value. Connect this pin directly to GND for SlotID = 0; or pull this pin up to 3.3Vaux for SlotID = 1.</p> <p>For add-in cards, connect this pin to the endpoint Package ID[1] field. Refer to the endpoint device datasheet for details.</p> <p>The Package ID[2:0] is a 3-bit field and is encoded in the NC-SI Channel ID as bits [7:5].</p> <p>Package ID[2] is defaults to 0b0 in the NC-SI specification, but is optionally configurable if the target silicon supports configuring this bit.</p> <p>Package ID[1] is connected to the SLOT_ID pin.</p>

			<p>Package ID[0] is set to 0b0 for Network Silicon #0. Package ID[1] is set to 0b1 for Network Silicon #1 in the case of an OCP NIC 3.0 card with two discrete silicon instances.</p> <p>As written in the NC-SI specification, up to four silicon devices are supported on the bus if only Package ID[1:0] is configurable (e.g. Package ID[2] is statically set to 0b0). Up to eight silicon devices are supported on the NC-SI bus if Package ID[2:0] are all configurable.</p> <p>For add-in cards with multiple endpoint devices, the SLOT_ID pin may be used to configure a different Package ID value so long as the resulting combination does not cause addressing interferences.</p> <p>For endpoint devices without NC-SI support, leave this pin as a no connect on the add-in card.</p>
--	--	--	--

Figure ~~1917~~: NC-SI Over RBT Connection Example



Note 1: For baseboard designs with a single Primary Connector, connect ARB_IN to ARB_OUT to complete the NC-SI hardware arbitration ring. For designs with multiple Primary Connectors, connect ARB_IN and ARB_OUT to an analog mux to complete the NC-SI arbitration ring based on the number of cards installed in the system.

Note 2: For add-in cards with two discrete endpoint silicon, the Package ID[0] bit shall be statically set based on its silicon instance. For example, the figure above shows Network Silicon #0 and Network Silicon #1. Network Silicon #0 has Package ID[0] = 0b0, Network Silicon #1 has Package ID[0] = 0b1.

3.5.3 Scan Chain Pins – OCP Bay (Primary Connector)

This section provides the pin assignments for the Scan Bus interface signals on the Primary Connector OCP Bay. The AC/DC specifications are defined in Section XXX. An example connection diagram is shown in [Figure 20](#) ~~Figure 18~~.

Table ~~1716~~ Pin Descriptions – Scan Chain

Signal Name	Pin #	Baseboard Direction	Signal Description
CLK	OCP_B6	Output	Scan clock. The CLK is an output pin from the baseboard to the add-in card. The CLK may run up to 12.5MHz.

			<p>For baseboard implementations, connect the CLK pin to the Primary Connector. Tie the CLK pin directly to GND if the scan chain is not used.</p> <p>For NIC implementations, the CLK pin must be connected to Shift Registers 0 & 1, and optionally to Shift Registers 2 & 3 (if implemented) as defined in the text and Figure 20Figure 18, below. Pull the CLK pin up to through a 1kOhm resistor.</p>
DATA_OUT	OCP_B5	Output	<p>Scan clock data output from the baseboard to the add-in card. This bit stream is used to shift in NIC configuration data.</p> <p>For baseboard implementations, connect the DATA_OUT pin to the Primary Connector. Tie the DATA_OUT pin directly to GND if the scan chain is not used.</p> <p>For NIC implementations, the DATA_OUT pin may be left floating if it is not used for add-in card configuration. Pull the DATA_OUT pin up to 3.3Vaux through a 1kOhm resistor.</p>
DATA_IN	OCP_B4	Input	<p>Scan clock data input to the baseboard. This bit stream is used to shift out NIC status bits.</p> <p>For baseboard implementations, the DATA_IN pin shall be pulled up to 3.3Vaux through a 10kOhm resistor to prevent the input signal from floating if a card is not installed. This pin may be left as a no connect if the scan chain is not used.</p>



			For NIC implementations, the DATA_IN scan chain is required. The DATA_IN connection to Shift Registers 0 & 1, as defined in the text and Figure 20 Figure 18 , are required.
LD#	OCP_B3	Output	<p>Scan clock shift register load. Used to latch configuration data on the add-in card.</p> <p>For baseboard implementations, the LD# pin shall be pulled up to 3.3Vaux through a 1kOhm resistor if the scan chain is not used to prevent the add-in card from erroneous data latching.</p> <p>For NIC implementations, the LD# pin implementation is required. The LD# pin must be connected to Shift Registers 0 & 1 as defined in the text and Figure 20Figure 18. Pull the LD# pin up to 3.3Vaux through a 1kOhm resistor.</p>

The scan chain provides side band status indication between the add-in card and the baseboard. The scan chain bit definition is defined in the two tables below. The scan chain data stream is 32-bits in length for both the DATA_OUT and the DATA_IN streams. The scan chain implementation is optional on the host, but is mandatory on all OCP NIC 3.0 cards. The scan chain components operates on the 3.3Vaux power domain.

The DATA_OUT bus is an output from the host. The DATA_OUT bus provides initial configuration options to the add-in card. At the time of this writing, the default implementation does not use the DATA_OUT stream and is not implemented on the NIC. However, all baseboard systems that implement the Scan Chain shall connect DATA_OUT between the platform and the Primary Connector for future-proofing NIC implementations and subsequent revisions of this specification.

Table 1817: Pin Descriptions – Scan Chain DATA_OUT Bit Definition

Byte.bit	DATA_OUT Field Name	Default Value	Description
0.[0..7]	RSVD	0b000000	Reserved. Byte 0 value is 0h00.
1.[0..7]	RSVD	0h00	Reserved. Byte 1 value is 0h00.
2.[0..7]	RSVD	0h00	Reserved. Byte 2 value is 0h00.
3.[0..7]	RSVD	0h00	Reserved. Byte 3 value is 0h00.

The DATA_IN bus is an input to the host and provides NIC status indication. The default implementation is completed with two 8-bit 74LV165 parallel in to serial out shift registers in a cascaded implementation. Up to four shift registers may be implemented to provide additional NIC status indication to the host platform.

DATA_IN shift registers 0 & 1 are mandatory for all cards. DATA_IN shift registers 2 & 3 are optional depending on the card type and fields being reported to the host. DATA_IN shift register 2 may be used to indicate future definitions of the scan chain bit stream. DATA_IN shift registers 3 (in conjunction with shift register 2) are required for reporting link/activity indication on card implementations with 5-8 ports.

The host should read the DATA_IN bus multiple (TBD) times to qualify the incoming data stream.

A 1kOhm pull up resistor shall be implemented on the NIC to the SER input of the last shift register on the DATA_IN scan chain to maintain a default bit value of 0b1 for unused bits for implementations using less than four shift registers.

Table 1918: Pin Descriptions – Scan Bus DATA_IN Bit Definition

Byte.bit	DATA_OUT Field Name	Default Value	Description
0.0	PRSNTB[0]#	0bX	PRSNTB[3:0]# value is mirrored from the Primary Connector.
0.1	PRSNTB[1]#	0bX	
0.2	PRSNTB[2]#	0bX	



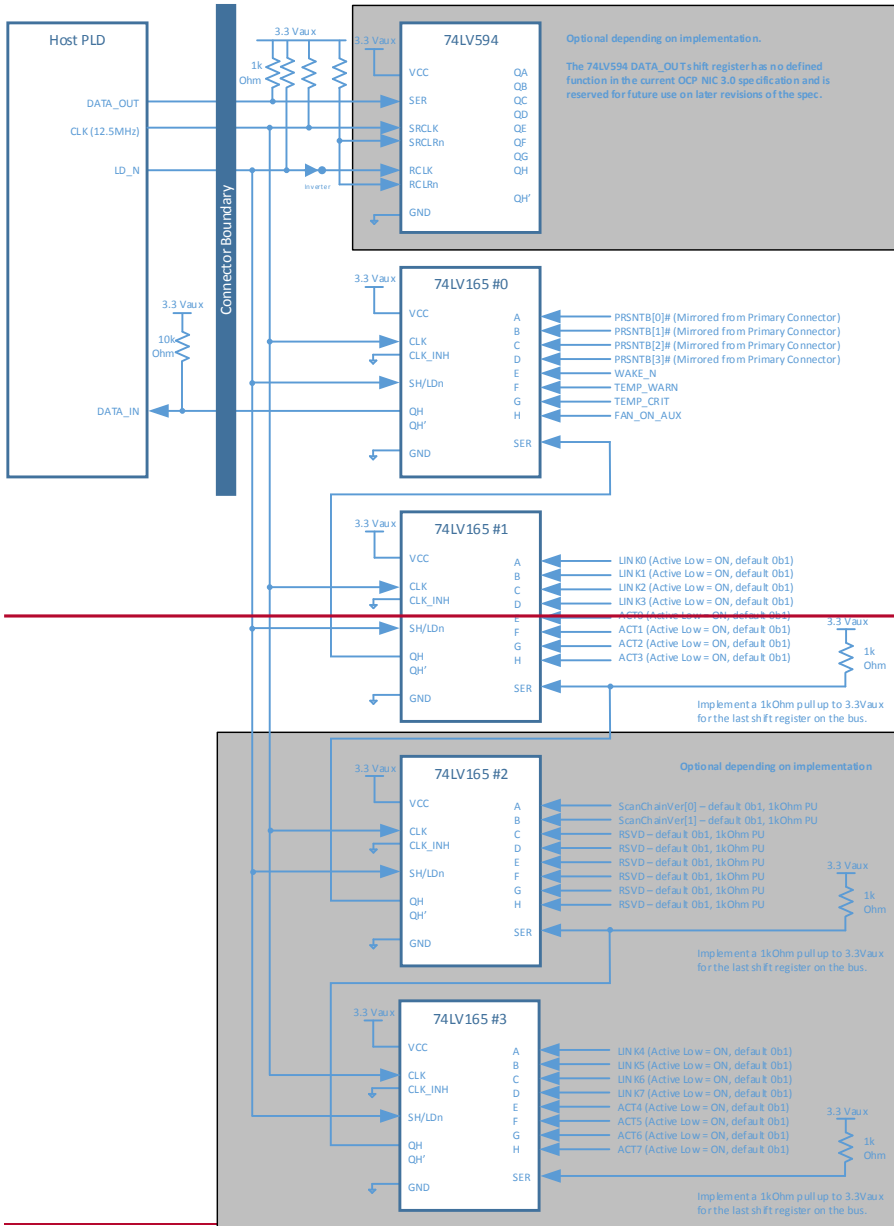
0.3	PRSNB[3]#	0bX	
0.4	WAKE_N	0bX	PCIe WAKE_N signal is mirrored from the Primary Connector.
0.5	TEMP_WARN	0b0	Temperature monitoring pin from the on-card thermal solution. This pin is asserted high when temperature sensor exceeds the temperature warning threshold.
0.6	TEMP_CRIT	0b0	Temperature monitoring pin from the on-card thermal solution. This pin is asserted high when temperature sensor exceeds the temperature critical threshold.
0.7	FAN_ON_AUX	0b0	When high, FAN_ON_AUX requests the system fan to be enabled for extra cooling in the S5 state.
1.0	LINK_ACT0	0b1	Port 0..3 link/activity indication. Active low. 0b0 – Link LED is illuminated on the host platform. 0b1 – Link LED is not illuminated on the host platform. Steady = link is detected on the port. Blinking = activity is detected on the port. <u>The blink rate should blink low for 50-500ms during activity periods.</u> Off = no link is detected on the port,the <u>physical link is down or disabled</u>
1.1	LINK_ACT1	0b1	
1.2	LINK_ACT2	0b1	
1.3	LINK_ACT3	0b1	
1.4	SPEED0ACT0	0b1	Port 0..3 speed indication. Active low. 0b0 – Port is linked at maximum speed. 0b1 – Port is not linked at the maximum speed or no link is present. Port 0..3 activity indication. Active low.
1.5	SPEED1ACT1	0b1	
1.6	SPEED2ACT2	0b1	
1.7	SPEED3ACT3	0b1	

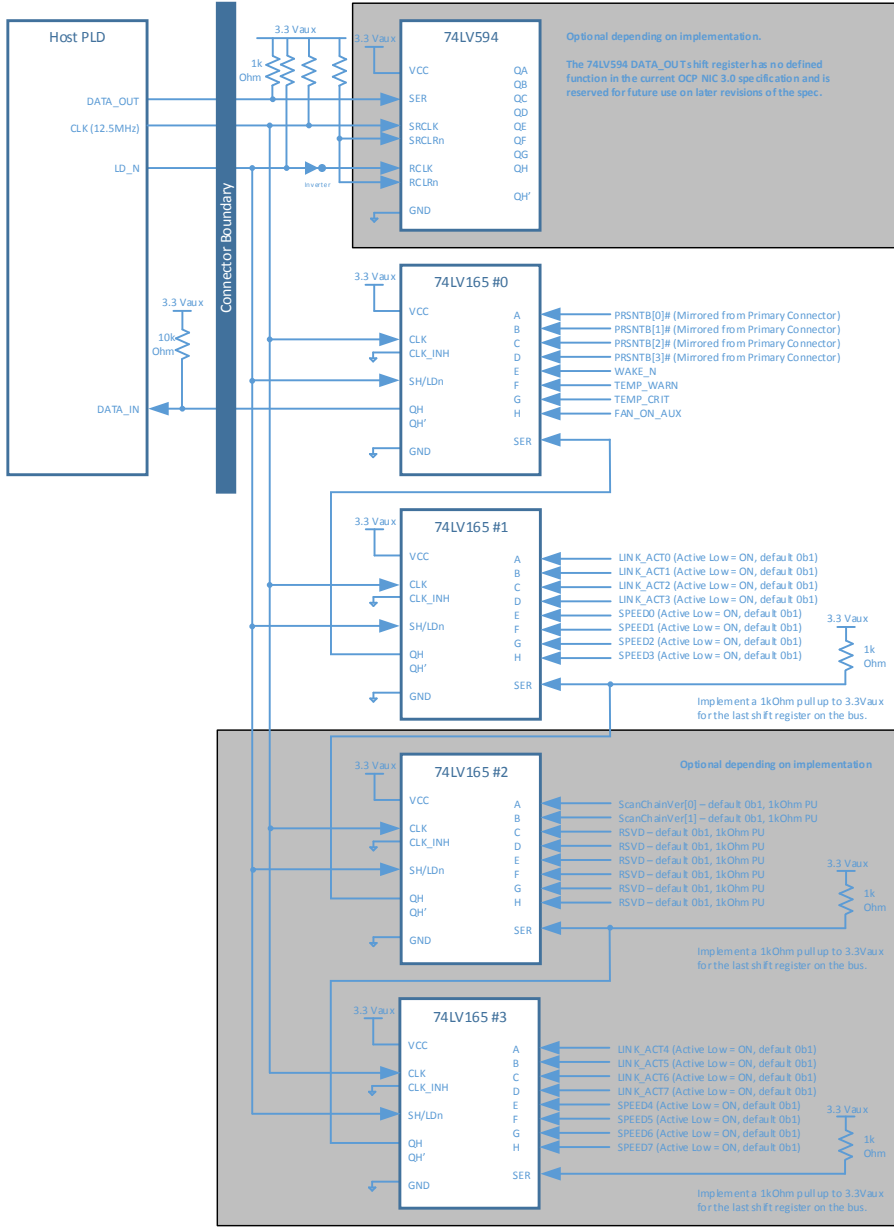
			<p>0b0 — Link LED is illuminated on the host platform.</p> <p>0b1 — Link LED is not illuminated on the host platform.</p> <p>Steady = no activity is detected on the port</p> <p>Blink = activity is detected on the port.</p> <p>Off = no link, see also LINK[3:0] LED bits.</p> <p>The LED blink duty cycle is dependent on the add-in card implementation. The recommended duty cycle is 50%.</p>
2.0	ScanChainVer[0]	0b1	<p>ScanChainVer[1:0] is used to indicate the scan chain bit definitions. The encoding is as follows:</p> <p>0b11 – Scan chain bit definitions version 1 corresponding to OCP 3.0 spec version 1.0.</p> <p>All other encodings are reserved.</p>
2.1	ScanChainVer[1]	0b1	
2.2	RSVD	0b1	<p>Byte 2 bits [2:7] are reserved. These bits shall default to the value of 0b1. These bits may be used in future versions of the scan chain.</p>
2.3	RSVD	0b1	
2.4	RSVD	0b1	
2.5	RSVD	0b1	
2.6	RSVD	0b1	
2.7	RSVD	0b1	
3.0	LINK_ACT4	0b1	<p><u>Port 4..7 link/activity indication. Active low.</u></p> <p><u>0b0 – Link LED is illuminated on the host platform.</u></p> <p><u>0b1 – Link LED is not illuminated on the host platform.</u></p>
3.1	LINK_ACT 5	0b1	
3.2	LINK_ACT 6	0b1	
3.3	LINK_ACT 7	0b1	



			<p><u>Steady</u> = link is detected on the port.</p> <p><u>Blinking</u> = activity is detected on the port.</p> <p>The blink rate should blink low for 50-500ms during activity periods.</p> <p><u>Off</u> = the physical link is down or disabled</p> <p>Port 4..7 link indication. Active low.</p> <p>0b0 — Link LED is illuminated on the host platform.</p> <p>0b1 — Link LED is not illuminated on the host platform.</p> <p>Steady = link is detected on the port.</p> <p>Off = no link is detected on the port.</p>
3.4	<u>ACT4SPEED4</u>	0b1	<p>Port 4..7 speed indication. Active low.</p> <p>0b0 – Port is linked at maximum speed.</p> <p>0b1 – Port is not linked at the maximum speed or no link is present.</p> <p>Port 4..7 activity indication. Active low.</p> <p>0b0 — Link LED is illuminated on the host platform.</p> <p>0b1 — Link LED is not illuminated on the host platform.</p> <p>Steady = no activity is detected on the port</p> <p>Blink = activity is detected on the port.</p> <p>Off = no link, see also LINK[3:0] LED bits.</p>
3.5	<u>SPEED5ACT5</u>	0b1	
3.6	<u>SPEED6ACT6</u>	0b1	
3.7	<u>SPEED7ACT7</u>	0b1	

Figure ~~2018~~: Scan Bus Connection Example





3.5.4 Primary Connector Miscellaneous Pins – OCP Bay (Primary Connector)



This section provides the miscellaneous pin assignments for the pins on the Primary Connector OCP Bay. The AC/DC specifications are defined in the PCIe CEM Specification, Rev 4.0 and Section 3.12. An example connection diagram is shown in Figure XXX.

Table ~~2019~~: Pin Descriptions – Miscellaneous 2

Signal Name	Pin #	Baseboard Direction	Signal Description
PWRBRK#	OCP_B2	Output, OD	<p>Power break. Active low, open drain.</p> <p>This signal is pulled up to 3.3Vaux on the add-in card with a minimum of 95kOhm and the baseboard with a stiffer resistance in-order to meet the timing specs as shown in the PCIe CEM Specification.</p> <p>This signal is driven low by the baseboard and is used to notify that an Emergency Power Reduction State is requested. The add-in card shall move to a lower power consumption state.</p>
NIC_PWR_GOOD	OCP_B1	Input	<p>NIC Power Good. Active high. This signal is driven by the add-in card.</p> <p>When high, this signal indicates that all of the add-in card power rails are operating within nominal tolerances.</p> <p>When low the add-in card power supplies are not yet ready or are in a fault condition.</p> <p>For baseboards, this pin may be connected to the platform I/O hub as a NIC power health status indication. This signal is pulled down</p>

			to ground with a 100kOhm resistor on the baseboard to prevent a false power good indication if no add-in card is present. For add-in cards this signal may be implemented by a cascaded power good or a discrete power good monitor output.
GND	OCP_A6 OCP_A10 OCP_A13 OCP_B10 OCP_B13	GND	Ground return; a total of 5 ground pins are on the OCP bay area.

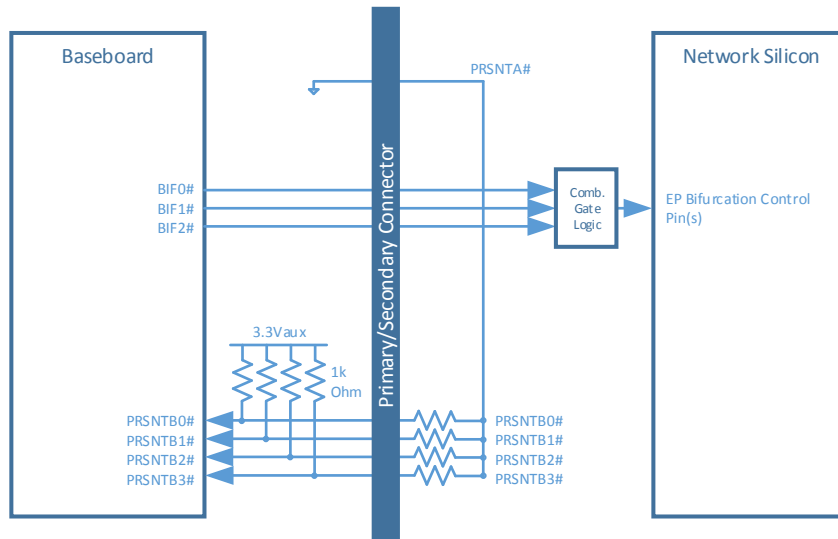
3.6 PCIe Bifurcation Mechanism

OCP3.0 baseboards and add-in cards support multiple bifurcation combinations. Single socket baseboards with a single or multiple root ports, as well as a multi-socket baseboards with a single or multiple root ports are supported. The bifurcation mechanism also supports add-in cards with a single or multiple end points. These features are accomplished via I/O pins on the Primary and Secondary connector:

- PRSNTA#, PRSNTB[3:0]#. The PRSNTA# pin connects to the PRSNTB# pins as a hard coded value on the add-in card. The encoding of the PRSNTB[3:0]# pins allows the baseboard to determine the PCIe Links available on the add-in card.
- BIF[3:0]#. The BIF# pin states are controlled by the baseboard and allows the baseboard to override the default end point bifurcation for silicon that support bifurcation. Additional combinatorial logic is required and is specific to the card silicon. The combinatorial logic is not covered in this specification.

The high level bifurcation connections are shown in [Figure 21](#)~~Figure 19~~.

Figure [21](#)~~19~~: PCIe Bifurcation Pin Connections Support



3.6.1 PCIe Add-in Card to Baseboard Bifurcation Configuration (PRSNTA#, PRSNTB[3:0]#)

The add-in card to baseboard configuration mechanism consists of four dual use pins (PRSNTB[3:0]#) on the add-in card and a grounded PRSNTA# pin on the baseboard. These pins provide card presence detection as well as mechanism to notify the baseboard of the pre-defined PCIe lane width capabilities. The PRSNTB[3:0]# pins are pulled up to 3.3Vaux on the baseboard and are active low signals. A state of 0b1111 indicates that no card is present in the system. Depending on the capabilities of the add-in card, a selection of PRSNTB[3:0]# signals may be strapped to the PRSNTA# signal and is pulled low by the baseboard. The encoding of the PRSNTB[3:0]# bits is shown in [Table 21](#) ~~Table 20~~ for x16 and x8 PCIe cards.

3.6.2 PCIe Baseboard to Add-in Card Bifurcation Configuration (BIF[2:0]#)

Three signals (BIF[2:0]#) are driven by the baseboard to notify requested bifurcation on the add-in card silicon. This allows the baseboard to set the lane configuration on the add-in card that supports multiple bifurcation options.

For example, a baseboard that has four separate hosts that support a 4 x4 connection, should appropriately drive the BIF[2:0]# pins per [Table 21](#)~~Table 20~~ and indicate to the add-in silicon to setup a 4 x4 configuration.

As previously noted, the BIF[2:0]# signals require additional combinatorial logic to decode the BIF[2:0]# value and appropriately apply it to the end-point silicon. The combinatorial logic is not covered in the specification as its implementation is specific to the vendor silicon used.

3.6.3 PCIe Bifurcation Decoder

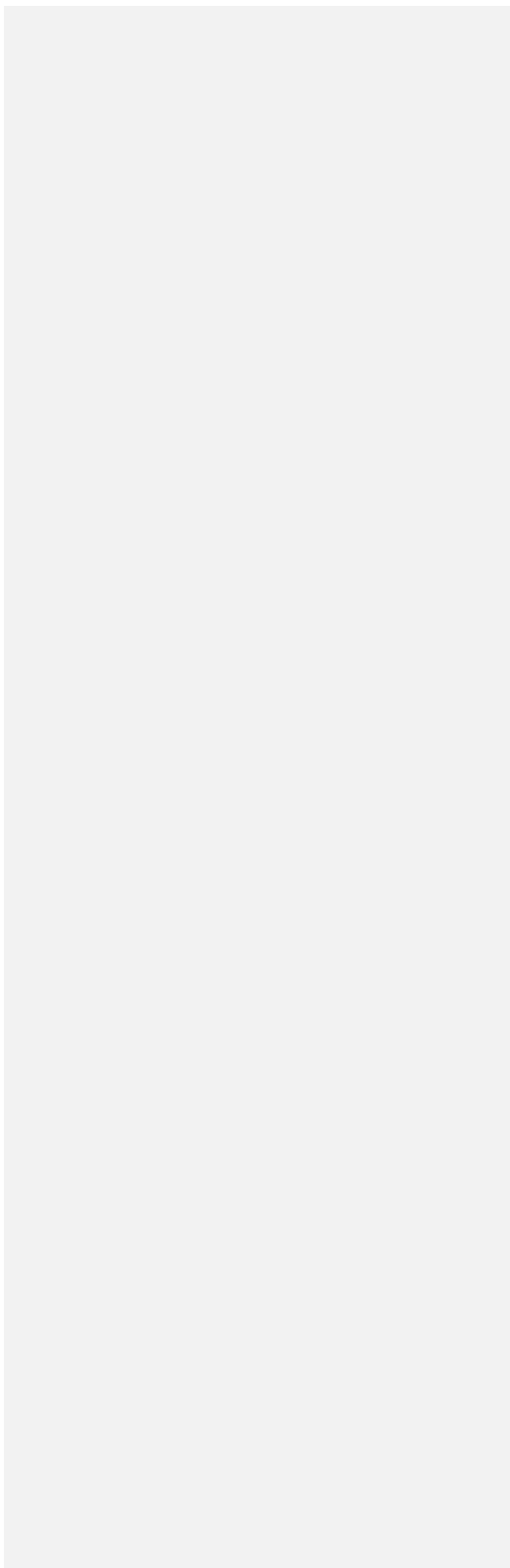
The combination of the PRSNTB[3:0]# and BIF[2:0]# pins deterministically sets the PCIe lane width for a given combination of baseboard and add-in cards. [Table 21](#)~~Table 20~~ shows the number of PCIe links and its width for known combinations of baseboards and add-in cards.

***Note:** The baseboard must disable PCIe lanes during the initialization phase if the number of detected PCIe links are greater than what is supported on the baseboard to prevent a nondeterministic solution. For example, if the baseboard only supports a 1 x16 connection, and the add-in card only supports a 2 x8 connection, the baseboard must disable PCIe lanes 8-15 to prevent any potential LTSSM issues during the discovery phase.



Table 2120: PCIe Bifurcation Decoder for x16 and x8 Card Widths

Minimum Required Card Edge	Card Short Name	Card Short Description	Host CPU Sockets	Host PCIe Links	System Support	System Encoding	1 Host 1 Upstream Socket	1 Host 1 or 2 Links (16x Bifurcation)	1 Host 1 or 2 Links (8x Bifurcation)	1 Host 2 Links	1 Host 4 Links	1 Host 2 Upstream Sockets	1 Host 4 Upstream Sockets	RSVD	RSVD	RSVD	Dual Host 2 Upstream Sockets (1 Socket per Host)	Quad Host 4 Upstream Sockets (1 Socket per Host)	Quad Host 4 Links	Quad Host 4 Links	Quad Host 4 Links	Quad Host 4 Links	
2C	1x8	1x8 (Host Processor)	1x8, 1x4, 1x2, 1x1	1x8	1x8	0x000	1x8	1x8	1x8	1x8	1x8	1x8	1x8	RSVD	RSVD	RSVD	2x8, 2x4, 2x2, 2x1	4x4, 4x2, 4x1	4x4	4x4	4x4	4x4	4x4
2C	1x4	1x4, 1x2, 1x1	1x4	1x4	1x4	0x110	1x4	1x4	1x4	1x4	1x4	1x4	1x4	RSVD	RSVD	RSVD	1x8	1x4	1x4	1x4	1x4	1x4	1x2
2C	1x2	1x2, 1x1	1x2, 1x1	1x2	1x2	0x110	1x2	1x2	1x2	1x2	1x2	1x2	1x2	RSVD	RSVD	RSVD	1x8	1x2	1x2	1x2	1x2	1x2	1x2
2C	1x1	1x1	1x1	1x1	1x1	0x110	1x1	1x1	1x1	1x1	1x1	1x1	1x1	RSVD	RSVD	RSVD	1x8	1x1	1x1	1x1	1x1	1x1	1x1
2C	1x8 Dpop-B	2x4, 2x2, 2x1	1x8, 1x4, 1x2, 1x1	1x8, 1x4, 1x2, 1x1	1x8, 1x4, 1x2, 1x1	0x101	1x8	1x8	1x8	1x8	1x8	1x8	1x8	RSVD	RSVD	RSVD	2x8, 2x4, 2x2, 2x1	4x4, 4x2, 4x1	4x4	4x4	4x4	4x4	4x2
4C	2x8 Dpop-B	4x4, 4x2, 4x1	2x4, 2x2, 2x1	2x8, 2x4, 2x2, 2x1	2x8, 2x4, 2x2, 2x1	0x101	2x8	2x8	2x8	2x8	2x8	2x8	2x8	RSVD	RSVD	RSVD	4x4, 4x2, 4x1	4x4	4x4	4x4	4x4	4x4	4x2
2C	1x8 Dpop-D	2x4, 2x2, 2x1	1x8, 1x4, 1x2, 1x1	1x8, 1x4, 1x2, 1x1	1x8, 1x4, 1x2, 1x1	0x100	1x8	2x4	2x4	1x8	1x8	1x8	1x8	RSVD	RSVD	RSVD	2x8	2x4	2x4	2x4	2x4	2x4	4x2
4C	1x8 Dpop-D	4x4, 4x2, 4x1	2x4, 2x2, 2x1	2x8, 2x4, 2x2, 2x1	2x8, 2x4, 2x2, 2x1	0x100	1x8	2x4	2x4	1x8	1x8	1x8	1x8	RSVD	RSVD	RSVD	4x4	4x4	4x4	4x4	4x4	4x4	4x2
2C	2x4	2x4, 2x2, 2x1	1x4, 1x2, 1x1	2x4	2x4	0x011	1x4	2x4	2x4	1x4	1x4	1x4	1x4	RSVD	RSVD	RSVD	2x4	2x4	2x4	2x4	2x4	2x4	2x2
2C	1x8	1x8 (Host Processor)	1x8	1x8	1x8	0x011	1x8	1x8	1x8	1x8	1x8	1x8	1x8	RSVD	RSVD	RSVD	1x8	1x8	1x8	1x8	1x8	1x8	1x2
2C	1x4	1x4, 1x2, 1x1	1x4	1x4	1x4	0x011	1x4	1x4	1x4	1x4	1x4	1x4	1x4	RSVD	RSVD	RSVD	1x8	1x4	1x4	1x4	1x4	1x4	1x2
2C	1x2	1x2, 1x1	1x2, 1x1	1x2	1x2	0x011	1x2	1x2	1x2	1x2	1x2	1x2	1x2	RSVD	RSVD	RSVD	1x8	1x2	1x2	1x2	1x2	1x2	1x2
2C	1x1	1x1	1x1	1x1	1x1	0x011	1x1	1x1	1x1	1x1	1x1	1x1	1x1	RSVD	RSVD	RSVD	1x8	1x1	1x1	1x1	1x1	1x1	1x1
4C	2x8 Dpop-A	2x4, 2x2, 2x1	1x8, 1x4, 1x2, 1x1	1x8, 1x4, 1x2, 1x1	1x8, 1x4, 1x2, 1x1	0x010	1x8	2x8	2x8	1x8	1x8	1x8	1x8	RSVD	RSVD	RSVD	2x8	2x8	2x8	2x8	2x8	2x8	2x2
4C	1x8 Dpop-B	2x4, 2x2, 2x1	1x8, 1x4, 1x2, 1x1	1x8, 1x4, 1x2, 1x1	1x8, 1x4, 1x2, 1x1	0x010	1x8	1x8	1x8	1x8	1x8	1x8	1x8	RSVD	RSVD	RSVD	2x8	2x8	2x8	2x8	2x8	2x8	2x2
4C	1x8 Dpop-C	4x4, 4x2, 4x1	2x4, 2x2, 2x1	2x8, 2x4, 2x2, 2x1	2x8, 2x4, 2x2, 2x1	0x000	1x8	1x8	1x8	1x8	1x8	1x8	1x8	RSVD	RSVD	RSVD	4x4	4x4	4x4	4x4	4x4	4x4	2x2
4C	4x4	4x4, 4x2, 4x1	2x4, 2x2, 2x1	2x8, 2x4, 2x2, 2x1	2x8, 2x4, 2x2, 2x1	0x001	1x4*	2x4*	2x4*	1x8	1x8	1x8	1x8	RSVD	RSVD	RSVD	2x4	2x4	2x4	2x4	2x4	2x4	4x2
RSVD	RSVD	RSVD	RSVD	RSVD	RSVD	0x000	RSVD	RSVD	RSVD	RSVD	RSVD	RSVD	RSVD	RSVD	RSVD	RSVD	RSVD	RSVD	RSVD	RSVD	RSVD	RSVD	RSVD



3.6.4 Bifurcation Detection Flow

[Need input and clarification from system vendors]

The following detection flow shall be used to determine the resulting link count and lane width based on the baseboard and add-in card configurations.

1. The baseboard reads the state of the PRSNTB[3:0]# pins. If the resulting value is not 0b1111, an add-in card is present.
2. Firmware determines the add-in card PCIe lane width capabilities per [Table 21](#) reading the PRSNTB[3:0]# pins.
3. The baseboard reconfigures the PCIe bifurcation on its ports to match the highest common lane width and lowest common link count on the card.
4. For cases where the baseboard request a link count override (such as requesting a 4-host baseboard requesting 4 x4 operation on a supported card that would otherwise default to a 2 x8 case), the BIF[0:2]# pins would be asserted as appropriate. Doing so assumes the add-in card supports the requested link override.
5. PERST# is deasserted after the >100ms window as defined by the PCIe specification. Refer to Section 3.12 for timing details.



3.6.5 PCIe Bifurcation Examples

For illustrative purposes, the following figures show several common bifurcation permutations.

Figure 22

in card that also supports x16. The PRSTNB[3:0]# state is 0b0111. The BIF[2:0]# state is 0b000 as there is no need to instruct the end-point network controller to a specific bifurcation. The PRSNTB encoding notifies the baseboard that this card is only capable of 1 x16. The single host baseboard determines that it is also capable of supporting 1 x16. The resulting link width is 1 x16.

~~Figure 20~~ illustrates a single host baseboard that supports x16 with a single controller add-in card that also supports x16. The PRSTNB[3:0]# state is 0b0111. The BIF[2:0]# state is 0b000 as there is no need to instruct the end-point network controller to a specific bifurcation. The PRSNTB encoding notifies the baseboard that this card is only capable of 1 x16. The single host baseboard determines that it is also capable of supporting 1 x16. The resulting link width is 1 x16.

Figure ~~220~~: Single Host (1 x16) and 1 x16 Add-in Card (Single Controller)

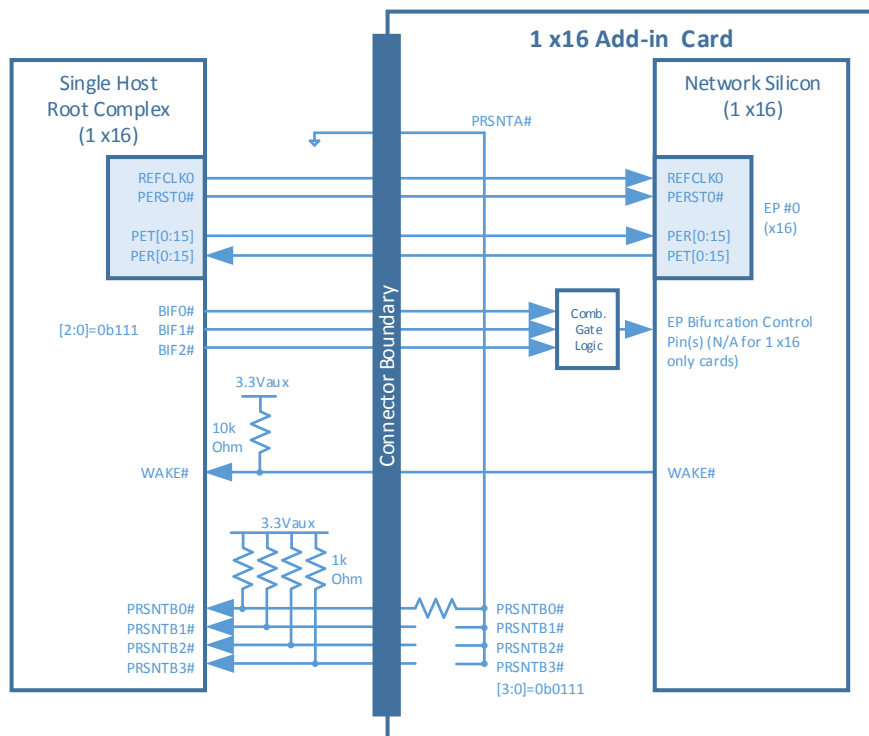


Figure 23 illustrates a single host baseboard that supports 2 x8 with a single in card that also supports 2 x8. The PRSNTB[3:0]# state is 0b0110. The BIF[2:0]# state is 0b111 as there is no need to instruct the end-point network controllers to a specific bifurcation. The PRSNTB encoding notifies the baseboard that this card is only capable of 2 x8. The single host baseboard determines that it is also capable of supporting 2 x8. The resulting link width is 2 x8.

Figure 23: Single Host (2 x8) and 2 x8 Add-in Card (Dual Controllers)

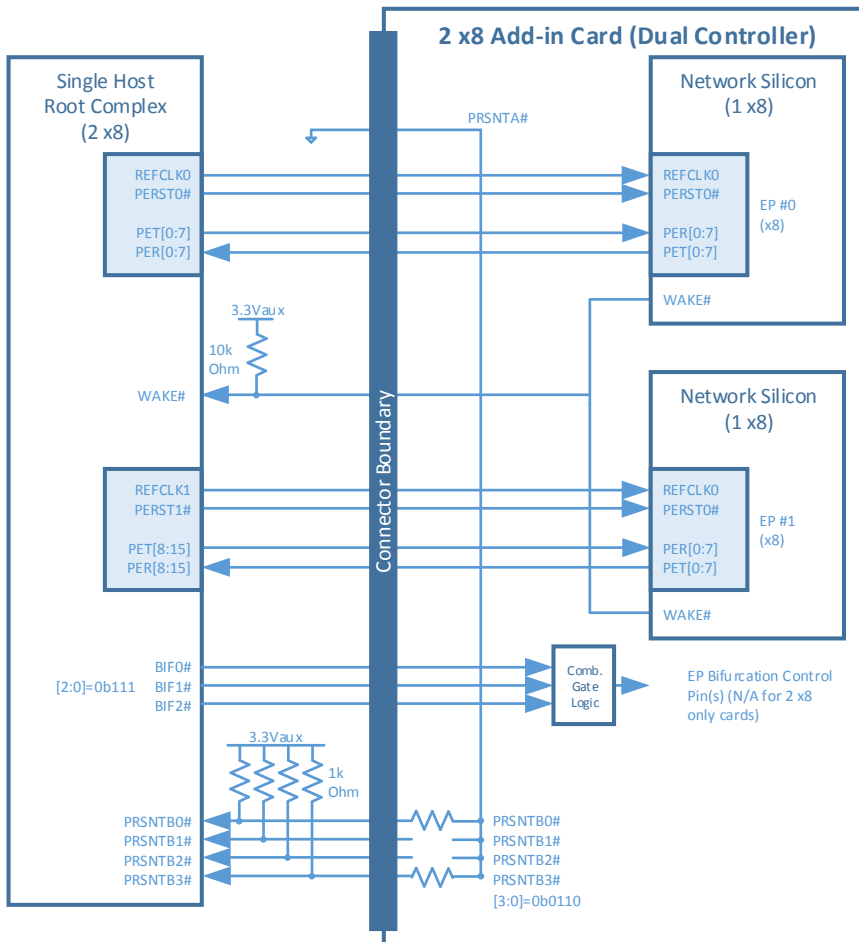


Figure 24 illustrates a four host baseboard that supports 4 x4 with a single card that supports 1 x16, 2 x8 and 4 x4. The PRSTNB[3:0]# state is 0b0011. The BIF[2:0]# state is 0b101 as the end point network controller is forced to bifurcate to 4 x4. The PRSNTB encoding notifies the baseboard that this card is only capable of 1 x16, 2 x8 and 4 x4. The four host baseboard determines that it is also capable of supporting 4 x4. The resulting link width is 4 x4.

Figure 2422: Four Hosts (4 x4) and 4 x4 Add-in Card (Single Controller)

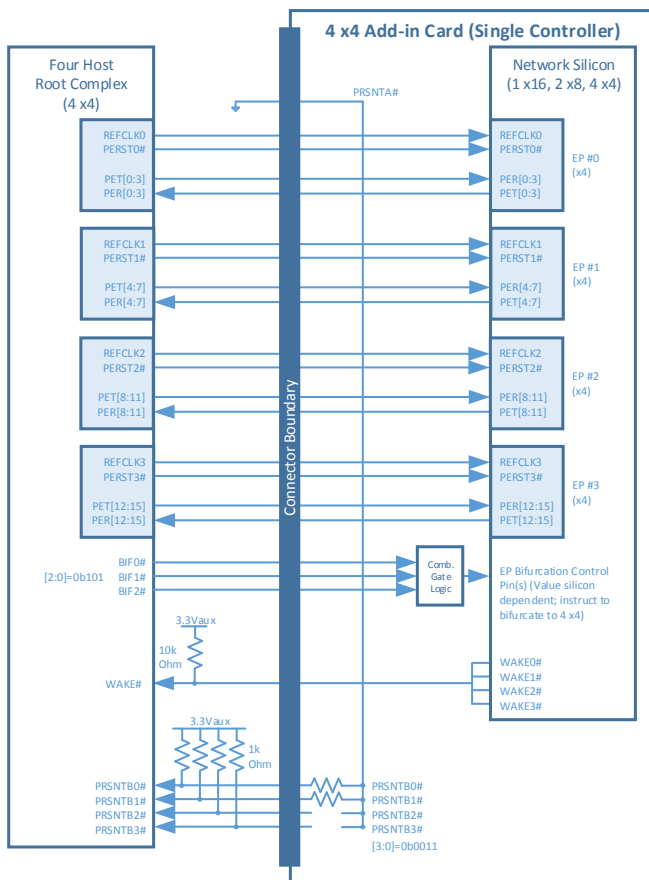


Figure 2523 illustrates a four host baseboard that supports 4 x4 with a four controller card that supports 4 x4. The PRSNTB[3:0]# state is 0b0011. The BIF[2:0]# state is 0b111 as there is no need to instruct the end-point network controllers to a specific bifurcation. The PRSNTB encoding notifies the baseboard that this card is only capable of 4 x4. The four host baseboard determines that it is also capable of supporting 4 x4. The resulting link width is 4 x4.

Figure 2523: Four Hosts (4 x4) and 4 x4 Add-in Card (Four Controllers)

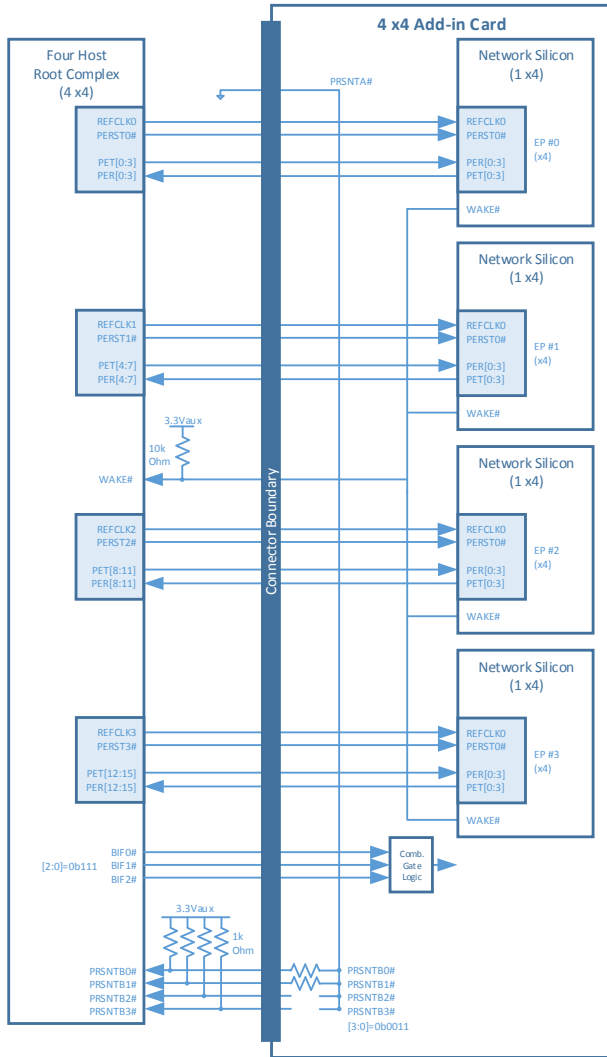
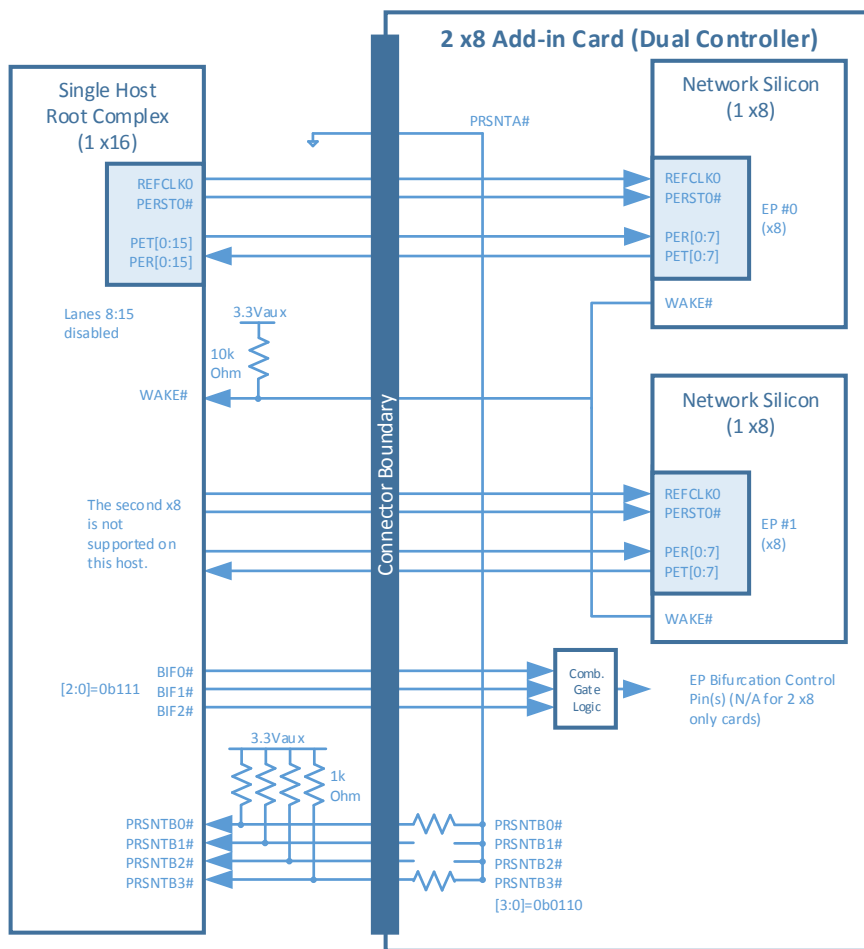


Figure 26 illustrates a single host baseboard that supports 1 x16 with a dual in card that supports 2 x8. The PRSTNB[3:0]# state is 0b0110. The BIF[2:0]# state is 0b111 as there is no need to instruct the end-point network controllers to a specific bifurcation. The PRSNTB encoding notifies the baseboard that this card is only capable of 2 x8. The four host baseboard determines that it is capable of 1x 16, but down shifts to 1 x8. The resulting link width is 1 x8 and only on endpoint 0.

Figure 26: Single Host with no Bifurcation (1 x16) and 2 x8 Add-in Card (Two Controllers)





3.7 PCIe Clocking Topology

The OCP NIC 3.0 specification allows for up to four PCIe REFCLKs on the Primary Connector and up to two PCIe REFCLKs on the Secondary Connector. In general, the association of each REFCLK is based on the PCIe Link number on a per connector basis and is shown in [Table 2221](#). Cards that implement both the Primary and Secondary connectors have a up to 6 REFCLKs.

Table 2221: PCIe Clock Associations

REFCLK #	Description	Availability (Connector)
REFCLK0	REFCLK associated with Link 0.	Primary and Secondary Connectors.
REFCLK1	REFCLK associated with Link 1.	Primary and Secondary Connectors.
REFCLK2	REFCLK associated with Link 2.	Primary Connector only.
REFCLK3	REFCLK associated with Link 3.	Primary Connector only.

For each add-in card, the following REFCLK connection rules must be followed:

- For a 1 x16 capable add-in card, REFCLK0 is used for lanes [0:15].
- For a 2 x8 capable add-in card, REFCLK0 is used for lanes [0:7] and REFCLK1 is used for lanes [8:15].
- For a 4 x4 capable add-in card, REFCLK0 is used for lanes [0:3], REFCLK1 is used for lanes [4:7], REFCLK2 is used for lanes [8:11] and REFCLK3 is used for lanes [12:15]. Pins for REFCLK2 and REFCLK3 are described in Section 3.5.1 and are located on the 28-pin OCP bay.

Figure 2725: PCIe Interface Connections for 1 x16 and 2 x8 Add-in Cards

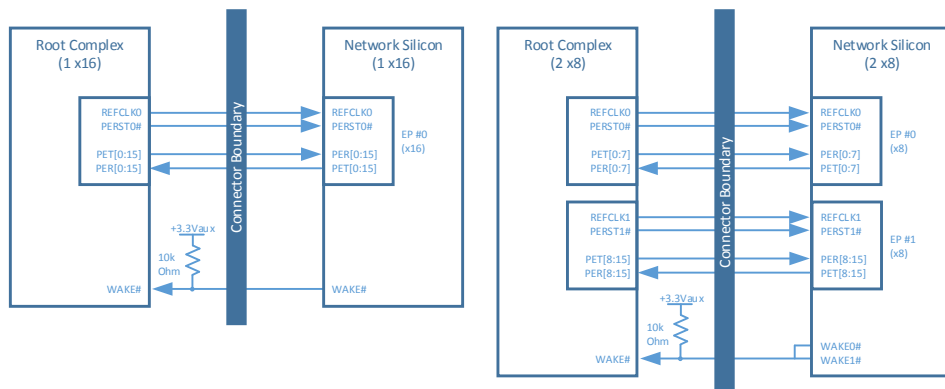
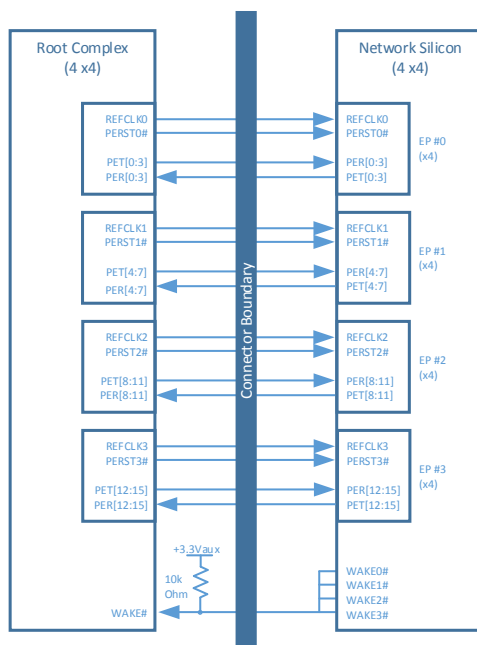


Figure 2826: PCIe Interface Connections for a 4 x4 Add-in Card





3.8 PCIe Bifurcation Results and REFCLK Mapping

For the cases where the baseboard and add-in card bifurcation are permissible, this section enumerates all of the supported PCIe link, lane and REFCLK mappings for each supported configuration. The bifurcation decoder is shown in Section 3.6.3.

Table 2322: Bifurcation for Single Host, Single Socket and Single Upstream Link
(BIF[2:0]#=0b000)

Min Lanes	Max Lanes	Host	Upstream Device	BIF[2:0]	PCIe Link #	PCIe Link	PCIe Lane 0	PCIe Lane 1	PCIe Lane 2	PCIe Lane 3	PCIe Lane 4	PCIe Lane 5	PCIe Lane 6	PCIe Lane 7	PCIe Lane 8	PCIe Lane 9	PCIe Lane 10	PCIe Lane 11	PCIe Lane 12	PCIe Lane 13	PCIe Lane 14	PCIe Lane 15	
2C	2C	1x8, 1x4, 1x2, 1x1	Host	Upstream Socket	0x0110	1x8	Link 0, Lane 0	Link 0, Lane 1	Link 0, Lane 2	Link 0, Lane 3	Link 0, Lane 4	Link 0, Lane 5	Link 0, Lane 6	Link 0, Lane 7									
2C	2C	1x4, 1x2, 1x1	Host	Upstream Socket	0x0110	1x4	Link 0, Lane 0	Link 0, Lane 1	Link 0, Lane 2	Link 0, Lane 3	Link 0, Lane 4	Link 0, Lane 5	Link 0, Lane 6	Link 0, Lane 7									
2C	2C	1x2, 1x1	Host	Upstream Socket	0x0110	1x2	Link 0, Lane 0	Link 0, Lane 1	Link 0, Lane 2	Link 0, Lane 3	Link 0, Lane 4	Link 0, Lane 5	Link 0, Lane 6	Link 0, Lane 7									
2C	2C	1x1	Host	Upstream Socket	0x0110	1x1	Link 0, Lane 0	Link 0, Lane 1	Link 0, Lane 2	Link 0, Lane 3	Link 0, Lane 4	Link 0, Lane 5	Link 0, Lane 6	Link 0, Lane 7									
2C	2C	1x8, 1x4, 1x2, 1x1	Host	Upstream Socket	0x0101	1x8	Link 0, Lane 0	Link 0, Lane 1	Link 0, Lane 2	Link 0, Lane 3	Link 0, Lane 4	Link 0, Lane 5	Link 0, Lane 6	Link 0, Lane 7									
2C	2C	2x8, 2x4, 2x2, 2x1	Host	Upstream Socket	0x0101	1x4	Link 0, Lane 0	Link 0, Lane 1	Link 0, Lane 2	Link 0, Lane 3	Link 0, Lane 4	Link 0, Lane 5	Link 0, Lane 6	Link 0, Lane 7									
4C	4C	2x4, 4x2, 4x1	Host	Upstream Socket	0x0100	1x4	Link 0, Lane 0	Link 0, Lane 1	Link 0, Lane 2	Link 0, Lane 3	Link 0, Lane 4	Link 0, Lane 5	Link 0, Lane 6	Link 0, Lane 7									
2C	2C	1x8, 1x4	Host	Upstream Socket	0x0100	1x8	Link 0, Lane 0	Link 0, Lane 1	Link 0, Lane 2	Link 0, Lane 3	Link 0, Lane 4	Link 0, Lane 5	Link 0, Lane 6	Link 0, Lane 7									
2C	2C	2x8, 2x4	Host	Upstream Socket	0x0100	1x4	Link 0, Lane 0	Link 0, Lane 1	Link 0, Lane 2	Link 0, Lane 3	Link 0, Lane 4	Link 0, Lane 5	Link 0, Lane 6	Link 0, Lane 7									
2C	2C	1x8, 1x4, 1x2, 1x1	Host	Upstream Socket	0x0101	1x8	Link 0, Lane 0	Link 0, Lane 1	Link 0, Lane 2	Link 0, Lane 3	Link 0, Lane 4	Link 0, Lane 5	Link 0, Lane 6	Link 0, Lane 7									
2C	2C	2x8, 2x4, 2x2, 2x1	Host	Upstream Socket	0x0101	1x4	Link 0, Lane 0	Link 0, Lane 1	Link 0, Lane 2	Link 0, Lane 3	Link 0, Lane 4	Link 0, Lane 5	Link 0, Lane 6	Link 0, Lane 7									
4C	4C	2x4, 4x2, 4x1	Host	Upstream Socket	0x0100	1x4	Link 0, Lane 0	Link 0, Lane 1	Link 0, Lane 2	Link 0, Lane 3	Link 0, Lane 4	Link 0, Lane 5	Link 0, Lane 6	Link 0, Lane 7									
2C	2C	1x8, 1x4, 1x2, 1x1	Host	Upstream Socket	0x0101	1x8	Link 0, Lane 0	Link 0, Lane 1	Link 0, Lane 2	Link 0, Lane 3	Link 0, Lane 4	Link 0, Lane 5	Link 0, Lane 6	Link 0, Lane 7									
2C	2C	2x8, 2x4, 2x2, 2x1	Host	Upstream Socket	0x0101	1x4	Link 0, Lane 0	Link 0, Lane 1	Link 0, Lane 2	Link 0, Lane 3	Link 0, Lane 4	Link 0, Lane 5	Link 0, Lane 6	Link 0, Lane 7									
4C	4C	2x4, 4x2, 4x1	Host	Upstream Socket	0x0100	1x4	Link 0, Lane 0	Link 0, Lane 1	Link 0, Lane 2	Link 0, Lane 3	Link 0, Lane 4	Link 0, Lane 5	Link 0, Lane 6	Link 0, Lane 7									
2C	2C	1x8, 1x4, 1x2, 1x1	Host	Upstream Socket	0x0101	1x8	Link 0, Lane 0	Link 0, Lane 1	Link 0, Lane 2	Link 0, Lane 3	Link 0, Lane 4	Link 0, Lane 5	Link 0, Lane 6	Link 0, Lane 7									
2C	2C	2x8, 2x4, 2x2, 2x1	Host	Upstream Socket	0x0101	1x4	Link 0, Lane 0	Link 0, Lane 1	Link 0, Lane 2	Link 0, Lane 3	Link 0, Lane 4	Link 0, Lane 5	Link 0, Lane 6	Link 0, Lane 7									
4C	4C	2x4, 4x2, 4x1	Host	Upstream Socket	0x0100	1x4	Link 0, Lane 0	Link 0, Lane 1	Link 0, Lane 2	Link 0, Lane 3	Link 0, Lane 4	Link 0, Lane 5	Link 0, Lane 6	Link 0, Lane 7									

3.9 Power Capacity and Power Delivery

There are four permissible power states: AC Power Off, ~~Management (FRU Only) ID Mode~~, Aux Power Mode (S5), and Main Power Mode (S0). The transition of these states is shown in ~~Figure 29~~ ~~Figure 27~~. The max available power envelopes for each of these states are defined in ~~Table 30~~.

Figure 2927: Baseboard Power Sequencing States

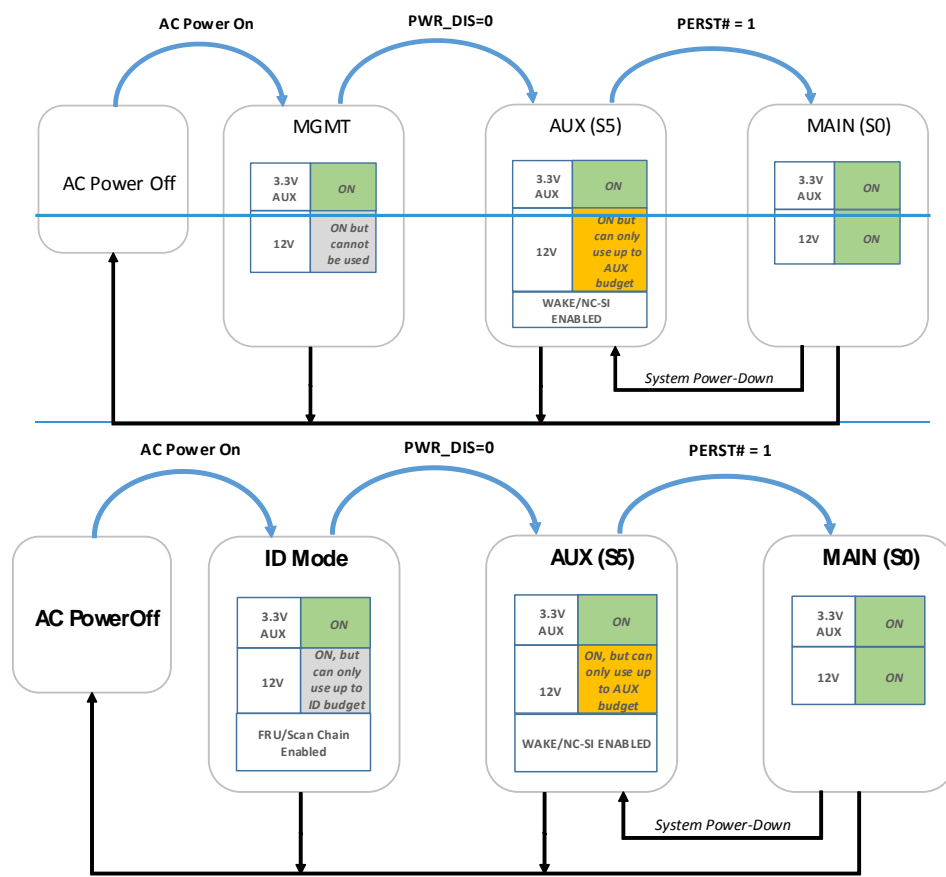


Table 3130: Power Envelopes States



Power State	PWRDIS	PERSTn	FRU	Scan Chain	RBT Link	3.3V	Max Power @12V
AC-AC Power Off	Low	Low					0W
Management-ID Mode(FRU only mode)	High	Low	X	X		X	X1W
Aux Power Mode (S5)	Low	Low	X	X	X	X	X35W
Main Power Mode (S0)	Low	High	X	X	X	X	X79.2W

3.9.1 AC Power Off

In AC power off mode, all power delivery has been turned off or disconnected from the baseboard.

3.9.2 Management-ID Mode(FRU Only Mode)

In the ~~Management (FRU Only) ID Mode~~, only 3.3V Aux is available for powering up management only functions. FRU accesses are only allowed in this mode.

3.9.3 Aux Power Mode (S5)

In Aux Power Mode provides both 3.3V Aux as well as 12V Aux is available. 12V Aux may be used to deliver power to the add-in card, but only up to the Aux budget of 35W.

3.9.4 Main Power Mode (S0)

In Main Power Mode provides both 3.3V and 12V (Main) across the OCP connector. The add-in card operates in full capacity. Up to 79.2W may be delivered on 12V, and 3.63W on the 3.3V pins.

3.10 ~~Add-in Card Input Capacitance~~ Power Supply Rail Requirements

The baseboard provides 3.3Vaux and 12Vaux/main to both the Primary and Secondary connectors. The rail requirements are leveraged from the PCIe CEM 4.0 specification. For OCP NIC 3.0 cards, the requirements are as follows:

Table ~~3231~~: [Baseboard Power Supply Rail Requirements](#)

Power Rail	30W Slot Small Card Hot Aisle	79.2W (Main Power Mode) 80W Slot Small Card Cold Aisle	150W Large Card Cold Aisle

3.3Vaux			
Voltage Tolerance	±9% (max)	±9% (max)	±9% (max)
Supply Current			
ID Mode	375mA (max)	375mA (max)	375mA (max)
Aux Mode	1.1A (max)	1.1A (max)	2.2A (max)
Main Mode	1.1A (max)	1.1A (max)	2.2A (max)
Capacitive Load	150µF (max)	150µF (max)	300µF (max)
		±9% (max)	
		1.1A (max)	
		150µF (max)	
12V			
Voltage Tolerance	±8% (max)	±8% (max)	±8% (max)
Supply Current			
ID Mode	100mA (max)	100mA (max)	100mA (max)
Aux Mode	1.3A (max)	3.3A (max)	6.3A (max)
Main Mode	2.5A (max)	6.6A (max)	12.5A (max)
Capacitive Load	1000µF (max)	2000µF (max)	4000µF (max)
		±8% (max)	
		6.6A (max)	
		2000µF (max)	

3.11 Hot Swap Considerations for 12V and 3.3V Rails

For baseboards that support system hot (powered on) add-in card insertions and extractions, the system implementer shall consider the use of hotswap controllers on both the 12Vmain/aux and 3.3Vaux pins to prevent damage to the baseboard or the add-in card. Hotswap controllers help with in-rush current limiting while also providing overcurrent protection, undervoltage and overvoltage protection capabilities.

The hotswap controller may gate the 12Vmain/aux and 3.3Vmain/aux based on the PRSNTB[3:0]# value. Per Section 3.6.3, a card is present in the system when the encoded value is not 0b1111. The PRSNTB[3:0]# can be AND'ed together and connected to the hotswap controller to accomplish this result. Per the OCP NIC 3.0 mechanical definition (Section **XXX**), the present pins are short pins and engage only when the card is positively seated.



Baseboards that do not support hot insertion, or hot extractions may opt to not implement these features.

3.12 Power Sequence Timing Requirements

The following figure shows the power sequence of PRSNTB[3:0]#, 3.3Vaux, 12Vaux/12Vmain relative to PWRDIS, BIF[2:0]#, PERSTn*, the add-in card power ramp and NIC_PWR_GOOD.

Figure ~~3028~~: Power Sequencing

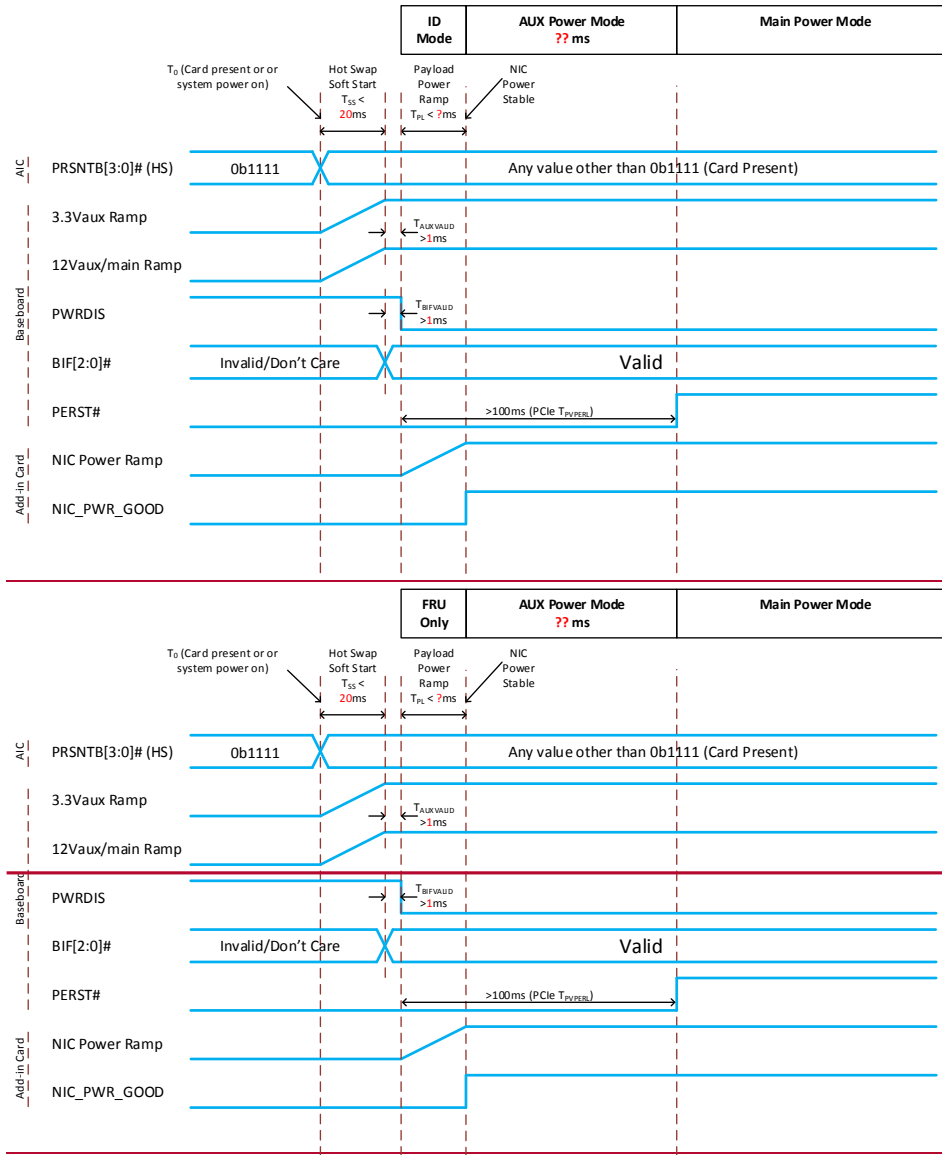


Table 3332: Power Sequencing Parameters



Parameter	Value	Units	Description
T _{SS}	20	ms	Max time between system 3.3Vaux and 12Vaux/main ramp to power stable.
T _{AUXVALID}	>1	ms	Min time between 3.3Vaux valid to PWRDIS assertion.
T _{BIFVALID}	>1	ms	Min time between BIF[2:0]# valid to PWRDIS assertion. The BIF[2:0]# value sets the add-in card bifurcation mode (if applicable)
T _{PL}	<?	ms	Max time between the NIC payload power ramp to NIC_PWR_GOOD assertion
T _{PVPERL}	>100	ms	Max time between PWRDIS deassertion and PERST# deassertion. This value is from the PCIe CEM Specification, Rev 4.0.

4 Management

4.1 SMBus Interface

The SMBus provides manageability of the add-in card.

4.2 NC-SI Sideband Interface

4.2.1 NC-SI addressing and Arb#

4.3 MAC Address Requirement

4.4 FRU EEPROM

4.4.1 Minimum EEPROM Size

4.4.2 EEPROM Map Definition

Editor's note [TN, 20171208]: the EEPROM map definition should include the card power class (e.g. be able to identify the max power required for 12V to the baseboard). This allows the baseboard to intelligently enable/disable the card based on the available baseboard power budget.

[4.4.24.4.3](#) **EEPROM** Address

4.5 FW Requirement (TBD)

4.6 Thermal Reporting Interface



5 Data Network Requirement

5.1 Network Booting (collect view from OEMs and hyperscale)

Mezzanine NIC shall support network booting in uEFI system environment. Mezzanine NIC shall support both IPv4 and IPv6 network booting.

6 Routing Guidelines and Signal Integrity Considerations

6.1 NC-SI Over RBT

Min Length: 2"

Max length: 4"

Impedance: 50 Ohm single ended

7 Thermal and Environmental

7.1 Environmental Requirements

The specific environment requirement is removed to allow the adoption of OCP Mezzanine NIC in systems with very different thermal requirement and boundary condition.

This Mezzanine card shall meet the same environmental requirements specified in the OCP systems that the Mezzanine card is in. The OCP system that uses OCP Mezzanine card shall define air flow direction, inlet air temperature, air flow (or speed) to the local area where Mezzanine card is at, and simulation boundary.

7.1.1 Thermal Simulation Boundary Example

Placeholder for Thermal Simulation Method. Using Facebook Intel® Motherboard V3.0 as example. Not covered by this update.

7.2 Shock & Vibration

This Mezzanine card shall meet the same shock & vibration requirements specified in updated Facebook OCP Intel® Motherboard V2.0 and V3.0 Design Specification.

7.3 Regulation

This Mezzanine card shall meet CE, CB, FCC Class A, WEEE, ROHS requirements.

